



THE DATASHEET OF AS8221-ASSP





AS8221

FlexRay Standard Transceiver

1 General Description

This document is subject to change without notice.

The AS8221 is a high speed automotive bus driver fully conforming to the FlexRay Electrical Physical Layer Specification V2.1 Rev B. The AS8221 operates as a bi-directional interface between the FlexRay Communication Controller and the twisted-pair copper wiring.

The AS8221 provides an optimized host controller interface consisting of three low-active pins. The Enable (EN) and Standby (STBN) input pins for mode handling by the microcontroller and the Error (ERRN) out pin where system, chip failures or status information are signalled to the microcontroller. Signalling logic high on the Enable and Standby pin the device will enter NORMAL mode in case no fault condition is given and in this mode the device is fully operational meaning FlexRay communication is possible. Additionally, a RECEIVE-ONLY mode is implemented, which can be accessed by the microcontroller where only FlexRay streams can be received in order to avoid unwanted disturbances on the FlexRay bus while listening to the bus traffic. In the low-power modes (STANDBY and SLEEP mode) very low power consumption is achieved.

In case of undervoltage at one of the supply voltages (VBAT, VCC, and VIO) the device will change its mode to a low-power mode (either STANDBY or SLEEP mode) and the device will signal an error accordingly. In case of low voltage is detected on both VBAT and VCC the device will enter the POWER-OFF mode, where no operation is possible. A safe mechanism from the low-power modes to POWER-OFF mode and vice versa is implemented ensuring that no deadlock can happen during the startup phase.

Ensuring application in safety critical environments a two wire bus-guardian interface is implemented where additional monitoring circuitries on the electronic-control-unit can activate and deactivate the transmitter and additionally on the receive enable output (RxEN) in low-power modes the wake conditions and in normal power modes the received FlexRay streams can be monitored.

A thermal sensor circuit with an integral shutdown mechanism prevents damage to the device in extreme temperature conditions. The symmetrical transient control for the high- and low-side driver for both the bus-minus (BM) and bus-plus (BP) line allows an ideal balance of communications over different network topologies, with excellent EMC performance.

2 Key Features

- Compliant with FlexRay Electrical Physical Layer Specification V2.1 Rev. B
- Data transfer up to 10 Mbps
- Excellent EMC performance. High common mode range ensure excellent EMI
- Interface for Bus Guardian or supervision circuits
- Automatic thermal shutdown protection
- Supports 12V and 24V systems with very low sleep current
- Integrated power management system
 - Two inhibit pins for external voltage supply control
 - Local wake-up input
 - Remote wake-up capability via FlexRay bus in low-power modes
- Supports 2.5V, 3V, 3.3V, 5V microcontrollers, automatic adaptation to digital interface levels
- Protection against damage due to short circuit conditions on the bus (positive and negative battery voltage)
- Operating temperature range -40°C to +125°C
- Lead-free SSOP20 package

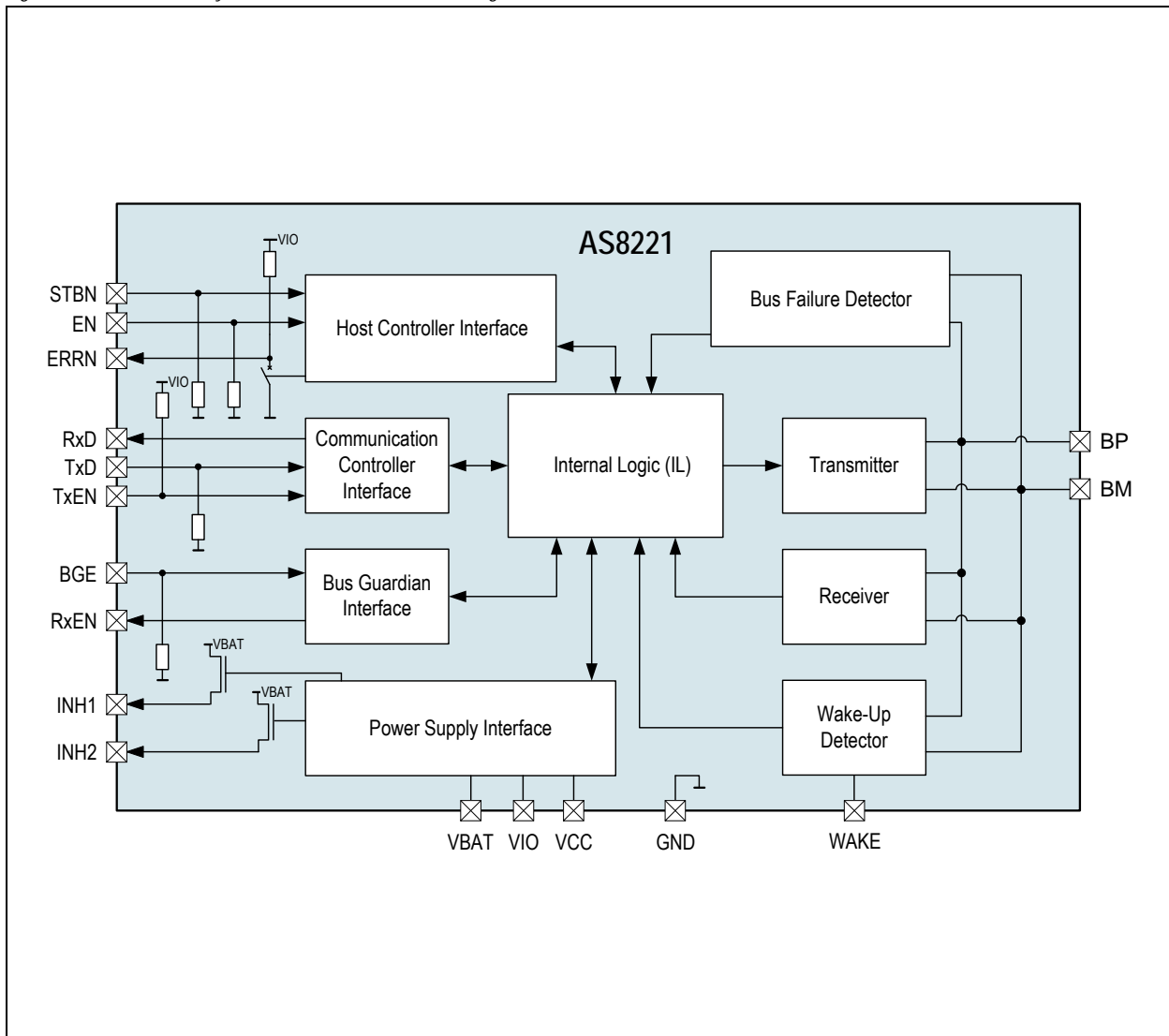
3 Applications

The AS8221 FlexRay Standard Transceiver is best fitting for automotive FlexRay nodes where bus wake-up and voltage regulator control for voltage supplies is needed.

The device addresses all ECUs connected to the permanent battery supply (clamp 30). The AS8221 can be used as only ECU wake-up component with very low power consumption in SLEEP mode.



Figure 1. AS8221 FlexRay Standard Transceiver Block Diagram





Contents

| | | |
|-------|---|----|
| 1 | General Description | 1 |
| 2 | Key Features..... | 1 |
| 3 | Applications..... | 1 |
| 4 | Pin Assignments | 5 |
| 4.1 | Pin Descriptions..... | 5 |
| 5 | Absolute Maximum Ratings | 6 |
| 6 | Electrical Characteristics..... | 7 |
| 7 | Typical Operating Characteristics | 13 |
| 8 | Detailed Description..... | 14 |
| 8.1 | Block Description..... | 14 |
| 8.2 | Events..... | 14 |
| 8.3 | Operating Modes..... | 14 |
| 8.3.1 | NORMAL Mode | 15 |
| 8.3.2 | RECEIVE-ONLY Mode..... | 15 |
| 8.3.3 | STANDBY Mode..... | 15 |
| 8.3.4 | GO-TO-SLEEP Mode | 15 |
| 8.3.5 | SLEEP Mode | 15 |
| 8.4 | Non Operating Mode | 15 |
| 8.4.1 | POWER-OFF..... | 15 |
| 8.5 | Undervoltage Events | 16 |
| 8.5.1 | Undervoltage/Voltage Recovery VBAT | 16 |
| 8.5.2 | Undervoltage/Voltage Recovery VIO | 16 |
| 8.5.3 | Undervoltage/Voltage Recovery VCC..... | 16 |
| 8.6 | Power On/Off Events..... | 16 |
| 8.7 | Wake-Up Events..... | 16 |
| 8.7.1 | Remote Wake-Up Event..... | 16 |
| 8.7.2 | Local Wake-Up Event | 17 |
| 9 | Application Information | 18 |
| 9.1 | Fail Silent Behavior..... | 19 |
| 9.1.1 | RxEN / BGE timeout..... | 19 |
| 9.1.2 | State Transitions due to Undervoltage Detection | 19 |
| 9.1.3 | State Transitions due to Voltage Recovery Detection | 19 |
| 9.2 | Mode Transitions | 19 |
| 9.2.1 | Operating Mode Transitions | 20 |
| 9.2.2 | ERRN Signalling..... | 22 |
| 9.3 | Loss of Ground | 22 |
| 9.4 | Error Flags..... | 22 |
| 9.4.1 | Undervoltage | 22 |
| 9.4.2 | Bus Error (BUSERR)..... | 22 |
| 9.4.3 | Short Circuit between BP and BM (BP_BM)..... | 22 |
| 9.4.4 | Over Temperature (OT)..... | 22 |
| 9.4.5 | TxEN_BGE Timeout (TxEN_TO)..... | 22 |
| 9.4.6 | Error Flag (ERROR) | 23 |

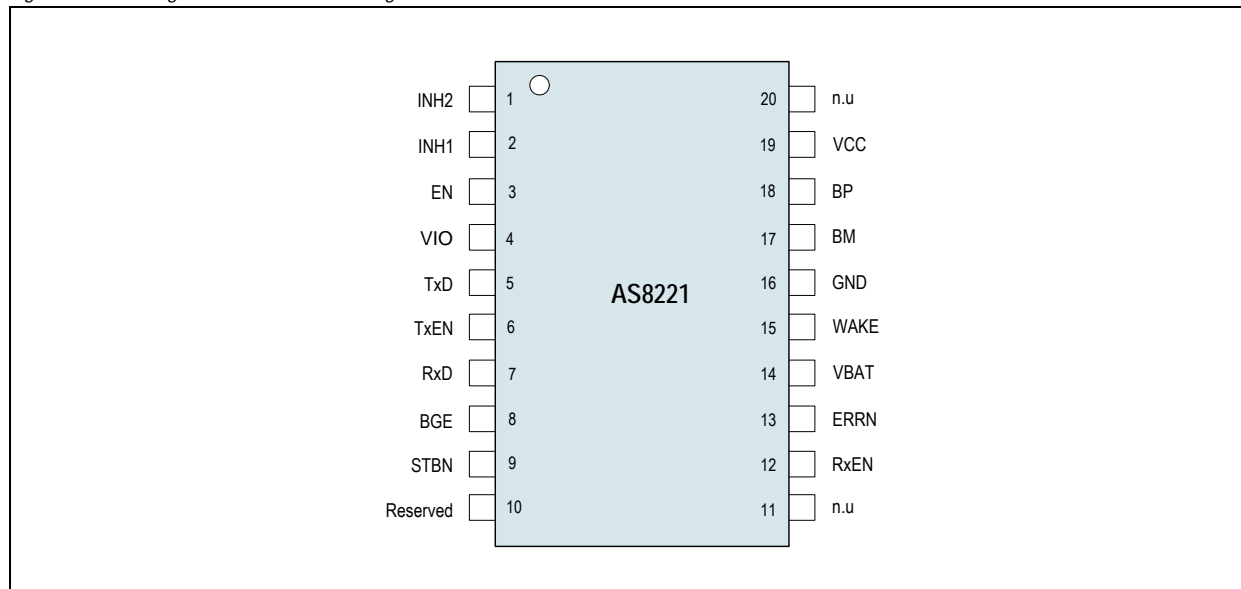


| | |
|--|----|
| 9.5 Status Flags..... | 23 |
| 9.5.1 Local Wake Flag (LWAKE)..... | 23 |
| 9.5.2 Remote Wake Flag (RWAKE)..... | 23 |
| 9.5.3 Power on Flag (PWON)..... | 23 |
| 9.6 Error Flags and Status Flags Read-Out..... | 23 |
| 9.6.1 Error and Status Flag Bit Order..... | 24 |
| 9.7 Bus Driver..... | 24 |
| 9.7.1 Bus States..... | 24 |
| 9.8 Transceiver Timing..... | 25 |
| 9.9 Transmitter..... | 26 |
| 9.10 Receiver..... | 27 |
| 9.10.1 Bus Activity and Idle Detection (only in NORMAL and RECEIVE-ONLY mode)..... | 28 |
| 9.10.2 Bus Data Detection (only in NORMAL and RECEIVE-ONLY mode)..... | 28 |
| 9.10.3 Receiver Test Signal..... | 29 |
| 9.11 Test Circuits..... | 30 |
| 9.12 Application Circuits..... | 31 |
| 10 Appendix..... | 32 |
| 10.1 FlexRay Functional Classes..... | 32 |
| 10.2 FlexRay Parameter Comparison..... | 32 |
| 11 Package Drawings and Markings..... | 39 |
| 12 Ordering Information..... | 41 |



4 Pin Assignments

Figure 2. Pin Assignments SSOP20 Package



4.1 Pin Descriptions

Table 1. Pin Descriptions

| Pin Name | Pin Number | Pin Type | Description |
|-----------------|------------|--|--|
| INH2 | 1 | Analog I/O | Analog Output. Inhibit 2 output for switching external voltage regulator |
| INH1 | 2 | | Analog Output. Inhibit 1 output for switching external voltage regulator |
| EN | 3 | Digital input with pull-down | Digital Input. Enable input |
| V _{IO} | 4 | Supply pad | Supply Voltage. I/O supply voltage |
| TxD | 5 | Digital input with pull-down | Digital Input. Transmit data input |
| TxEN | 6 | Digital input with pull-up | Digital Input. Transmitter enable input |
| RxD | 7 | Digital output | Digital Output. Receive data output |
| BGE | 8 | Digital input with pull-down | Digital Input. Bus guardian enable input |
| STBN | 9 | | Digital Input. Standby input |
| Reserved | 10 | Analog/digital input/output with pull-down | To be connected to GND or to be unconnected |
| Not used | 11 | - | |
| RxEN | 12 | Digital output | Digital Output. Receive data enable output |
| ERRN | 13 | | Digital Output. Error diagnosis output and wake status output |
| VBAT | 14 | Supply pad | Supply Voltage. Battery supply voltage |
| WAKE | 15 | Analog I/O | Analog Input. Local wake-up input |
| GND | 16 | Supply pad | Ground |
| BM | 17 | Analog I/O | Analog Input/Output. Bus line Minus |
| BP | 18 | | Analog Input/Output. Bus line Plus |
| V _{CC} | 19 | Supply pad | Supply voltage |
| Not used | 20 | - | |



5 Absolute Maximum Ratings

Stresses beyond those listed in [Table 2](#) may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in [Electrical Characteristics on page 7](#) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

| Parameter | Min | Max | Units | Notes |
|---|------|------------|-------|--|
| Battery Supply Voltage (VBAT) | -0.3 | +50 | V | |
| Supply Voltage (VCC) | -0.3 | +7.0 | V | |
| Supply Voltage (VIO) | -0.3 | +7.0 | V | |
| DC Voltage at EN, STBN, ERRN, TxD, RxD, TxEN, BGE, RxEN | -0.3 | VIO + 0.3 | V | VIO < VCC |
| DC Voltage on pin WAKE, INH1, INH2 | -0.3 | VBAT + 0.3 | | |
| DC Voltage at BP and BM | -40 | +50 | V | |
| Input current (latchup immunity) | -100 | 100 | mA | According to JEDEC 78 |
| Electrostatic discharge (VESD) | ±4 | | kV | BP, BM, VBAT and Wake pin according AEC-Q100-002 (HBM) |
| | ±2 | | kV | All other pins according to AEC-Q100-002 (HBM) |
| | ±3 | | kV | BP and BM according to FlexRay Physical Layer EMC Measurement Specification Version 3.0 |
| | ±500 | | V | On all pins AEC-Q100-011 (Charge Device Model) |
| | ±750 | | V | Corner pins AEC-Q100-011 (Charge Device Model) |
| | ±100 | | V | AEC-Q100-003 (Machine Model) |
| Transient voltage on BP, BM | -200 | +200 | V | According to ISO7637 part3 test pulses a and b; class C; RL=45Ω, CL= 100 pF; (see Figure 18 on page 30). |
| Transient voltage on VBAT | -200 | +200 | V | According to ISO7637 part2 test pulses 1, 2, 3a and 3b; class C; RL=45Ω, CL= 100pF; (see Figure 18 on page 30). |
| | +6.5 | +50 | V | According to ISO7637 part2 test pulse 4; class C; RL=45Ω, CL= 100pF; (see Figure 18 on page 30). |
| | | +50 | | According to ISO7637 part2 test pulse 5b; class C; RL=45Ω, CL= 100pF; (see Figure 18 on page 30). |
| Total power dissipation (all supplies and outputs) | | 150 | mW | |
| Storage temperature | -55 | +150 | °C | |
| Junction temperature | -40 | +150 | °C | |
| Package body temperature | | 260 | °C | The reflow peak soldering temperature (body temperature) specified is in accordance with <i>IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices"</i> . The lead finish for Pb-free leaded packages is matte tin (100% Sn). |
| Humidity non-condensing | 5 | 85 | % | |
| Moisture Sensitivity Level | 3 | | | Represents a maximum floor life time of 168h |



6 Electrical Characteristics

$T_{vj} = -40$ to $+150$ °C, $V_{CC} = +4.75V$ to $+5.25V$, $V_{BAT} = 5.5V$ to $+50V$, $V_{IO} = +2.2$ to V_{CC} , $R_L = 45\Omega$, $C_L = 100$ pF, unless otherwise specified.

Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--------------------------|--|---|--------------|--------------|--------------|---------------|
| Supply Voltage | | | | | | |
| T_{AMB} | Ambient temperature | | -40 | +25 | +125 | °C |
| V_{CC-VIO} | Difference of supplies | | -0.1 | | 3.05 | V |
| I_{BAT} | VBAT current consumption | VBAT=12V; low-power modes $T_{vj} < 125^\circ\text{C}$ (see footnote 1) | 0 | 26 | 50 | μA |
| | | VBAT=12V; low-power modes $T_{vj} < 150^\circ\text{C}$ | 0 | | 100 | μA |
| | | Non-low-power modes | 0 | 0.15 | 1 | mA |
| I_{CC} | VCC current consumption | Low-power Modes $V_{CC} = 0V$ to $+5.25V$ (see footnote 1) | -5 | 8 | 20 | μA |
| | | Non-low-power modes: NORMAL, driver enabled; | 0 | 29 | 45 | mA |
| | | Non-low-power modes: NORMAL, driver enabled; $R_{BUS} = \infty\Omega$ | 0 | 7 | 15 | mA |
| | | Non-low-power modes: RECEIVE-ONLY | 0 | 2.0 | 10 | mA |
| I_{IO} | VIO current consumption | Low-power modes $V_{IO} = 0V$ to $+5.25V$ | -5 | 1 | 5 | μA |
| | | Non-low power modes | 0 | 15 | 1000 | μA |
| State Transitions | | | | | | |
| t_{STBN_RxD} | Delay STBN high to RxD high with wake flag set | | 1 | 9 | 50 | μs |
| t_{STBN_RxE} | Delay STBN high to RxE high with wake flag set | | 1 | 9 | 50 | μs |
| t_{SLEEP_INH1} | Delay STBN high to INH1 high | INH1 high = 80% VBAT | 1 | 11 | 50 | μs |
| $t_{STANDBY_INH2}$ | Delay STBN high to INH2 high | INH2 high = 80% VBAT | 1 | 11 | 50 | μs |
| t_{SLEEP} | GO-TO-SLEEP hold time | INH1 low = 20% VBAT | 10 | 26 | 70 | μs |
| Transmitter | | | | | | |
| $V_{BUS_DIFF_D0}$ | Differential bus voltage low in NORMAL mode (Data0) | $V_{BPdata0} - V_{BMdata0}$; $40 \leq R_L \leq 55\Omega$ | -2 | -1 | -0.6 | V |
| $V_{BUS_DIFF_D1}$ | Differential bus voltage high in NORMAL mode (Data1) | $V_{BPdata1} - V_{BMdata1}$; $40 \leq R_L \leq 55\Omega$ | 0.6 | 1 | 2 | V |
| ΔV_{BUS_DIFF} | Matching between Data0 and Data1 differential bus voltage in NORMAL mode | $V_{BUS_DIFF_D0} - V_{BUS_DIFF_D1}$ $40 \leq R_L \leq 55\Omega$ | -200 | 0 | 200 | mV |
| $V_{BUS_COM_D0}$ | Common mode bus voltage in case of Data0 in non-low-power modes | $V_{BPdata0}/2 + V_{BMdata0}/2$ $40 \leq R_L \leq 55\Omega$ | 0.4 * VCC | 0.5 * VCC | 0.6 * VCC | V |
| $V_{BUS_COM_D1}$ | Common mode bus voltage in case of Data1 in non-low-power modes | $V_{BPdata1}/2 + V_{BMdata1}/2$ $40 \leq R_L \leq 55\Omega$ | 0.4 * VCC | 0.5 * VCC | 0.6 * VCC | V |



Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--|--|--|------|-----|-------|-------|
| ΔV_{BUS_COM} | Matching between Data0 and Data1 common mode voltage | $V_{BUS_COM_D0} - V_{BUS_COM_D1}$ $40 \leq R_L \leq 55\Omega$ | -200 | 0 | 200 | mV |
| $V_{BUS_DIFF_Idle}$ | Absolute differential bus voltage in bus idle mode | Load on BM/BM: $40\Omega \parallel 100pF$ | | 0 | 30 | mV |
| $IBP_{BMSHORTMax}$ $IBM_{BPShortMax}$ | Absolute max current when BP is shorted to BM | $V_{BP} = V_{BM}$ | | 35 | +100 | mA |
| $IBP_{GNDShortMax}$ | Absolute max current when BP is shorted to GND | $V_{BP} = 0V$ | | 48 | +100 | mA |
| $IBM_{GNDShortMax}$ | Absolute max current when BM is shorted to GND | $V_{BM} = 0V$ | | 48 | +100 | mA |
| $IBP_{-5VShortMax}$ | Absolute max current when BP is shorted to -5 V | $V_{BP} = -5V$ | | 48 | +100 | mA |
| $IBM_{-5VShortMax}$ | Absolute max current when BM is shorted to -5 V | $V_{BM} = -5V$ | | 48 | +100 | mA |
| $IBP_{27VShortMax}$ | Absolute max current when BP is shorted to 27 V | $V_{BP} = 27V$ | | 71 | +100 | mA |
| $IBM_{27VShortMax}$ | Absolute max current when BM is shorted to 27 V | $V_{BM} = 27V$ | | 71 | +100 | mA |
| $IBP_{48VShortMax}$ | Absolute max current when BP is shorted to 48 V | $V_{BP} = 48V$ | | 72 | +100 | mA |
| $IBM_{48VShortMax}$ | Absolute max current when BM is shorted to 48 V | $V_{BM} = 48V$ | | 72 | +100 | mA |
| t_{TxD_BUS01} | Delay time from TxD to BUS positive edge | $t_{TxD_RISE} = 5ns$ | | 22 | 50 | ns |
| t_{TxD_BUS10} | Delay time from TxD to BUS negative edge | $t_{TxD_FALL} = 5ns$ | | 22 | 50 | ns |
| $t_{TxD_MISMATCH}$ | Delay time from TxD to BUS mismatch | $t_{TxD_BUS10} - t_{TxD_BUS01}$ | -4 | 0 | 4 | ns |
| t_{BUS10} | Fall time differential bus voltage | 80% - 20% of V_{BUS} | 3.75 | 12 | 18.75 | ns |
| t_{BUS01} | Rise time differential bus voltage | 20% - 80% of V_{BUS} | 3.75 | 12 | 18.75 | ns |
| $t_{TxEN_BUS_Idle_Active}$ | Delay time from TxEN to bus active | | | 14 | 50 | ns |
| $t_{TxEN_BUS_Active_Idle}$ | Delay time from TxEN to bus idle | | | 10 | 50 | ns |
| $t_{TxEN_MISMATCH}$ | Delay time from TxEN to bus mismatch | $ t_{TxEN_BUS_Idle_Active} - t_{TxEN_BUS_Active_Idle} $ | | 4 | 50 | ns |
| $t_{BGE_BUS_Idle_Active}$ | Delay time from BGE to bus active | | | 15 | 50 | ns |
| $t_{BGE_BUS_Active_Idle}$ | Delay time from BGE to bus idle | | | 11 | 50 | ns |
| $t_{BUS_Idle_Active}$ | Differential bus voltage transition time: idle to active | | | 5 | 30 | ns |
| $t_{BUS_Active_Idle}$ | Differential bus voltage transition time: active to idle | | | 2 | 30 | ns |
| $t_{TxEN_timeout}$ | TxEN timeout | | 1.5 | 4.9 | 15 | ms |



Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|------------------------------------|---|---|----------------|----------------|----------------|-----------|
| Receiver | | | | | | |
| R_{BP}, R_{BM} | BP, BM input resistance | Idle mode; $R_{BUS} = \infty$ | 10 | 25 | 40 | $K\Omega$ |
| R_{DIFF} | BP, BM differential input resistance | Idle mode; $R_{BUS} = \infty$ | 20 | 50 | 80 | $K\Omega$ |
| V_{BPidle}, V_{BMidle} | Idle voltage in non-low-power modes on pin BP, BM | Non-low-power modes; $V_{TxEN} = V_{IO}$ Load on BM/BM: $40\Omega \parallel 100pF$ | $0.4 * V_{CC}$ | $0.5 * V_{CC}$ | $0.6 * V_{CC}$ | V |
| $V_{BPidle_low}, V_{BMidle_low}$ | Idle voltage in low-power modes on pin BP, BM | Low-power modes Load on BM/BM: $40\Omega \parallel 100pF$ | -0.2 | 0 | +0.2 | V |
| I_{BPidle} | Absolute idle output current on pin BP | $-40V < V_{BP} < 50V$ | 0 | 2 | 7.5 | mA |
| I_{BMidle} | Absolute idle output current on pin BM | $-40V < V_{BM} < 50V$ | 0 | 2 | 7.5 | mA |
| I_{BPleak}, I_{BMleak} | Absolute leakage current, when not powered | $V_{BP} = V_{BM} = 5V, V_{CC} = 0V,$ $V_{BAT} = 0V; V_{IO} = 0V$ | 0 | 7 | +25 | μA |
| $V_{BUSActiveHigh}$ | Activity detection differential input voltage high | Non-low-power modes; $V_{RECEIVE_COM}$: $-10V < (V_{BP}, V_{BM}) < 15V$ | 150 | 225 | 400 | mV |
| $V_{BUSActiveLow}$ | Activity detection differential input voltage low | Non-low-power modes; $V_{RECEIVE_COM}$: $-10V < (V_{BP}, V_{BM}) < 15V$ | -400 | -225 | -150 | mV |
| V_{Data1} | Data1 detection differential input voltage | Pre-condition: activity already detected. Non-low-power modes; $V_{RECEIVE_COM}$: $-10V < (V_{BP}, V_{BM}) < 15V$ | 150 | 225 | 300 | mV |
| V_{Data0} | Data0 detection differential input voltage | Pre-condition: activity already detected. Non-low-power modes; $V_{RECEIVE_COM}$: $-10V < (V_{BP}, V_{BM}) < 15V$ | -300 | -225 | -150 | mV |
| $V_{DataErr}$ | Mismatch between Data0 and Data1 differential input voltage | $2 \times (V_{Data0} - V_{Data1}) / (V_{Data0} + V_{Data1})$ (see footnote 2) | | | 10 | % |
| $V_{RECEIVE_COM}$ | Max. common mode voltage range when receiving | Non-low-power modes | -10 | | +15 | V |
| t_{BUS_RxD10} | Delay from BUS to RxD negative edge | $C_{RxD} = 15 pF$ (see footnote 3) | | 36 | 80 | ns |
| t_{BUS_RxD01} | Delay from BUS to RxD positive edge | $C_{RxD} = 15 pF$ (see footnote 3) | | 36 | 80 | ns |
| t_{BIT} | Bit time | $C_{RxD} = 15 pF$ (see footnote 3) | 54 | | | ns |
| t_{RxD_ASYM} | Delay time from BUS to RxD mismatch | $C_{RxD} = 15 pF$; $ t_{BUS_RxD10} - t_{BUS_RxD01} $ (see footnote 3) (see footnote 4) | | 0 | 5 | ns |
| t_{RxD_FALL} | Fall time RxD voltage | 80% - 20% of V_{RxD} ; $C_{RxD} = 15 pF$ (see footnote 3) | | 2 | 5 | ns |



Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-------------------------------|---|---|------|------|------|-------|
| t_{RxD_RISE} | Rise time RxD voltage | 20% - 80% of VRxD; CRxD=15 pF (see footnote 3) | | 2 | 5 | ns |
| $t_{BUSIdleDetection}$ | Idle detection time | V _{BUS} : 400mV → 0V | 50 | 173 | 200 | ns |
| $t_{BUSActivityDetection}$ | Activity detection time | V _{BUS} : 0V → 400mV | 100 | 173 | 250 | ns |
| $t_{BUSIdleReaction}$ | Idle reaction time | V _{BUS} : 400mV → 0V | 50 | 192 | 300 | ns |
| $t_{BUSActivityReaction}$ | Activity reaction time | V _{BUS} : 0V → 400mV | 100 | 200 | 350 | ns |
| Wake-Up Detector | | | | | | |
| t_{BWU_D0} | Data0 detection time in remote wake-up pattern | -10V < (V _{BP} , V _{BM}) < 15V | 1 | 2 | 4 | μs |
| t_{BWU_Idle} | Idle or Data1 detection time in remote wake-up pattern | -10V < (V _{BP} , V _{BM}) < 15V | 1 | 2 | 4 | μs |
| t_{BWU_Detect} | Total remote wake-up detection time | -10V < (V _{BP} , V _{BM}) < 15V | 48 | 73 | 140 | μs |
| V _{BWUTH} | Bus wake-up detection threshold | -10V < (V _{BP} , V _{BM}) < 15V | -300 | -250 | -150 | mV |
| V _{LWUTH} | Local wake-up detection threshold | | 2 | 2.8 | 4 | V |
| I _{LWUL} | Low level input current on local WAKE pin | V _{BAT} = 12V; V _{LWAKE} = 2V for t < t _{LWUFilter} | -20 | -10 | -5 | μA |
| I _{LWUH} | High level input current on local WAKE pin | V _{BAT} = 12V; V _{LWAKE} = 4V for t < t _{LWUFilter} | 5 | 11 | 20 | μA |
| t _{LWUFilter} | Local wake filter time | | 1 | 20 | 40 | μs |
| Supply Voltage Monitor | | | | | | |
| V _{BATTHH} | VBAT undervoltage recovery threshold | | 3.5 | 4 | 4.5 | V |
| V _{BATTHL} | VBAT undervoltage detection threshold | | 2.5 | 3 | 3.5 | V |
| V _{CCTHH} | VCC under-voltage recovery threshold | | 3.5 | 4 | 4.5 | V |
| V _{CCTHL} | VCC undervoltage detection threshold | | 2.5 | 3 | 3.5 | V |
| V _{IOTHH} | VIO undervoltage recovery threshold | | 1.25 | 1.6 | 2.0 | V |
| V _{IOTHL} | VIO undervoltage detection threshold | | 0.75 | 1.1 | 1.5 | V |
| t _{UV_DETECT} | Detection time for undervoltage at V _{BAT} , V _C , V _{IO} | | 100 | 300 | 700 | ms |
| t _{UV_REC} | Detection time for undervoltage recovery at V _{BAT} , V _C , V _{IO} | | 0.7 | 2 | 5 | ms |
| Bus Error Detection | | | | | | |
| I _{THL} | Absolute bus current for low current detection | NORMAL mode, Transmitter enabled | | 5 | | mA |
| I _{THH} | Absolute bus current for high current detection | NORMAL mode, Transmitter enabled | | 40 | | mA |



Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---|---|--|----------------|-----------------|----------------|--------------|
| V_{SHORT} | Differential voltage on BP and BM for detecting short circuit between bus lines | NORMAL mode, Transmitter enabled | | 225 | | mV |
| t_{BUS_ERROR} | Bus error detection time | NORMAL mode, Transmitter enabled | | 20 | | μ s |
| Over Temperature | | | | | | |
| OT_{TH} | Over temperature threshold | | 150 | 171 | 180 | $^{\circ}$ C |
| OT_{TL} | Over temperature hysteresis | | 10 | 13 | 20 | $^{\circ}$ C |
| Power Supply Interface | | | | | | |
| ΔV_{OINH} | High level voltage drop on INH1, INH2 | $I_{INH} = 0.2\text{mA}$, $V_{BAT} = 5.5\text{V}$ | 0 | 0.15 | 0.8 | V |
| $ I_{IL} $ | Leakage current | SLEEP mode, $V_{INH} = 0\text{V}$ | | 0 | 5 | μ A |
| Communication Controller Interface | | | | | | |
| V_{TxDIH} | Threshold for detecting TxD as on logical high | | | $0.48 * V_{IO}$ | $0.7 * V_{IO}$ | V |
| V_{TxDIL} | Threshold for detecting TxD as on logical low | | $0.3 * V_{IO}$ | $0.48 * V_{IO}$ | | V |
| I_{TxDIH} | TxD high level input current | | 30 | 52 | 100 | μ A |
| I_{TxDIL} | TxD low level input current | | -5 | 0 | 5 | μ A |
| V_{TxENIH} | Threshold for detecting TxEN as on logical high | | | $0.48 * V_{IO}$ | $0.7 * V_{IO}$ | V |
| V_{TxENIL} | Threshold for detecting TxEN as on logical low | | $0.3 * V_{IO}$ | $0.48 * V_{IO}$ | | V |
| I_{TxENIH} | TxEN high level input current | | -5 | 0 | 5 | μ A |
| I_{TxENIL} | TxEN low level input current | | -100 | -50 | -30 | μ A |
| $V_{RxD OH}$ | RxD high level output voltage | $I_{RxD} = -4\text{mA}$, $V_{IO} = 5\text{V}$ | $0.8 * V_{IO}$ | $0.9 * V_{IO}$ | $1.0 * V_{IO}$ | V |
| $V_{RxD OL}$ | RxD low level output voltage | $I_{RxD} = 4\text{mA}$, $V_{IO} = 5\text{V}$ | 0 | $0.1 * V_{IO}$ | $0.2 * V_{IO}$ | V |
| Host Interface | | | | | | |
| V_{STBNIH} | Threshold for detecting STBN as on logical high | | | $0.48 * V_{IO}$ | $0.7 * V_{IO}$ | V |
| V_{STBNIL} | Threshold for detecting STBN as on logical low | | $0.3 * V_{IO}$ | $0.48 * V_{IO}$ | | V |
| I_{STBNIH} | STBN high level input current | | 30 | 52 | 100 | μ A |
| I_{STBNIL} | STBN low level input current | | -5 | 0 | 5 | μ A |
| $t_{STBN_DEB_LP}$ | STBN de-bouncing time low-power modes | | 0.1 | 1 | 40 | μ s |
| $t_{STBN_DEB_NLP}$ | STBN de-bouncing time non-low-power modes | | 0.1 | 1 | 2 | μ s |
| V_{ENIH} | Threshold for detecting EN as on logical high | | | $0.48 * V_{IO}$ | $0.7 * V_{IO}$ | V |
| V_{ENIL} | Threshold for detecting EN as on logical low | | $0.3 * V_{IO}$ | $0.48 * V_{IO}$ | | V |
| I_{ENIH} | EN high level input current | | 30 | 50 | 100 | μ A |
| I_{ENIL} | EN low level input current | | -5 | 0 | 5 | μ A |



Table 3. Electrical Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-------------------------------|--|--------------------------------|----------------|-----------------|----------------|---------|
| $t_{EN_DEB_LP}$ | EN de-bouncing time low-power modes | | 0.1 | 1 | 40 | μs |
| $t_{EN_DEB_NLP}$ | EN de-bouncing time non-low-power modes | | 0.1 | 1 | 2 | μs |
| V_{ERRNOH} | ERRN high level output voltage | $I_{ERRN} = -4mA, V_{IO} = 5V$ | $0.8 * V_{IO}$ | $0.9 * V_{IO}$ | $1.0 * V_{IO}$ | V |
| V_{ERRNOL} | ERRN low level output voltage | $I_{ERRN} = 4mA, V_{IO} = 5V$ | 0 | $0.1 * V_{IO}$ | $0.2 * V_{IO}$ | V |
| Bus Guardian Interface | | | | | | |
| V_{BGEIH} | Threshold for detecting BGE as on logical high | | | $0.48 * V_{IO}$ | $0.7 * V_{IO}$ | V |
| V_{BGEIL} | Threshold for detecting BGE as on logical low | | $0.3 * V_{IO}$ | $0.48 * V_{IO}$ | | V |
| I_{BGEIH} | BGE high level input current | | 30 | 51 | 100 | μA |
| I_{BGEIL} | BGE low level input current | | -5 | 0 | 5 | μA |
| V_{RxENOH} | RxEN high level output voltage | $I_{RxEN} = -4mA, V_{IO} = 5V$ | $0.8 * V_{IO}$ | $0.9 * V_{IO}$ | $1.0 * V_{IO}$ | V |
| V_{RxENOL} | RxEN low level output voltage | $I_{RxEN} = 4mA, V_{IO} = 5V$ | 0 | $0.1 * V_{IO}$ | $0.2 * V_{IO}$ | V |
| Read Out Interface | | | | | | |
| $t_{RO_EN_ERRN}$ | Propagation delay falling edge EN to ERRN | | | 2 | 4.5 | μs |
| $t_{RO_EN_TIMEOUT}$ | error-read-out timeout | | 25 | 50 | 100 | μs |

1. EN, STBN, ERRN, TxD, RxD, TxEN, BGE, RxEN, LWAKE, INH1, INH2: open
2. Test condition: $(V_{BP} + V_{BM}) / 2 = 2,5V \pm 5\%$
3. For test signal (see Figure 17)
4. Guaranteed at specified bit time t_{BIT}



7 Typical Operating Characteristics

Figure 3. Bus Differential Voltage

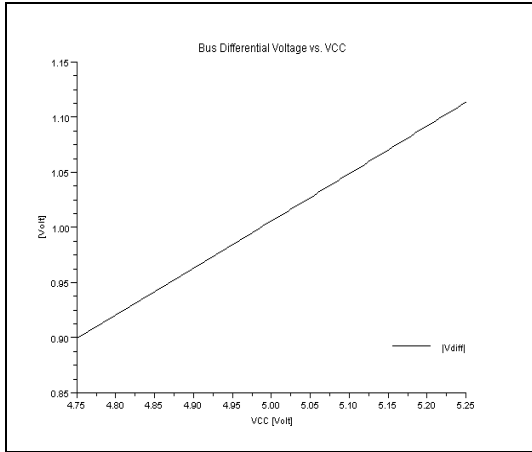


Figure 4. Bus Absolute Voltage

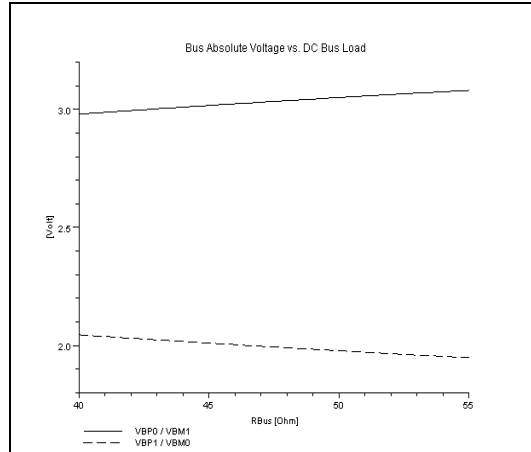


Figure 5. Bus Differential Voltage

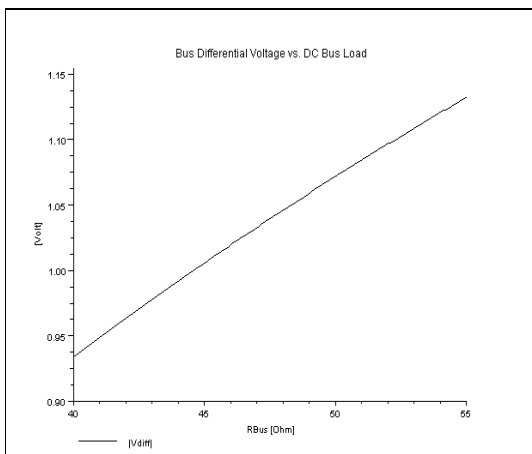
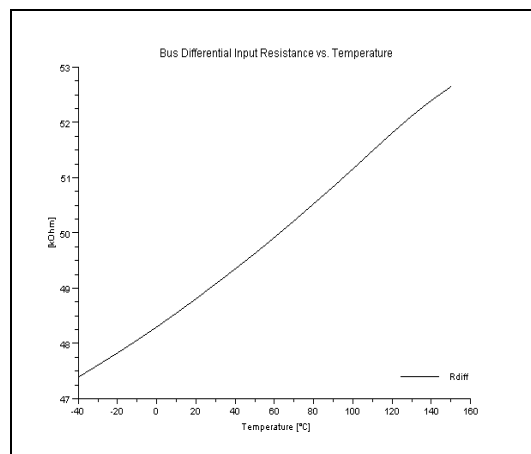


Figure 6. Bus Differential Input Resistance





8 Detailed Description

The AS8221 is a FlexRay Transceiver operating as an interface between the Communication Controller and the wired bus lines. The AS8221 is designed to extend the application range for high speed and safety critical time triggered bus systems in an automotive environment. The drivers are short circuit protected against the positive and negative supply voltage to increase the robustness and reliability of automotive systems. The AS8221 operates at baudrates up to 10 Mbps.

8.1 Block Description

The AS8221 consists of 9 functional blocks (see Figure 1):

Table 4. Functional Blocks

| Functional Block | Short Description |
|---|--|
| Host Controller Interface (HCI) | Digital interface between the Transceiver and the host controller (HC) The host interface comprises the read-out handler, which delivers failure and status information via the ERRN pin to the host controller. |
| Communication Controller Interface (CCI) | Digital interface between the Transceiver and the FlexRay communication controller (CC) |
| Bus Guarding Interface (BGI) | Digital interface between the Transceiver and the FlexRay bus guardian (BG) or monitoring circuitry. |
| Power Supply Interface (PSI) | The power supply interface consists of the voltage monitor (VM) with two analog inhibit outputs switching external voltage supplies. |
| Internal Logic (IL) | The digital signals from the functional blocks of the device are fed into the internal logic where the forwarding of FlexRay messages from analog side to digital interfaces and vice versa is done. The state machine is embedded in the Internal Logic and the handling of error, wake, and power-on flags is executed herein. |
| Bus Failure Detector (BFD) Temperature Protection (TP) | The bus failure detector is directly connected to the bus pins, in order to detect several external failure conditions which may occur on the bus. The temperature protection turns off the output driver when reaching the specified internal temperature in order to protect the device. |
| Transmitter | The transmitter provides the differential signalling according the FlexRay standard on the bus pins. |
| Receiver | The Receiver captures FlexRay valid signals at the bus pins and provides the received data streams to the Internal Logic. |
| Wake-Up Detector (WUD) | The wake-up detector recognizes valid wake-up frames on the bus, recognizes a wake signal on the local WAKE pin and signals valid wake-up events to the Internal Logic. |

8.2 Events

Transitions in order to change between the operation modes are possible only if events are detected. The device supports three type of events, events on the host controller interface (STBN, EN), detection of undervoltage or supply voltage recovery and wake events. Mode changes are only performed upon detected events.

8.3 Operating Modes

The AS8221 provides the following operating modes:

- NORMAL: non-low-power mode
- RECEIVE-ONLY: non-low-power mode
- STANDBY: low-power mode
- GO-TO-SLEEP: low-power mode
- SLEEP: low-power mode



8.3.1 NORMAL Mode

In this mode the Transceiver is able to send and receive data signals on the bus. TxEN and BGE enables and disables the transmission of data streams. INH1 and INH2 outputs are set high. RxD reflects bus data and bus state. The error-read-out-mechanism is enabled. In NORMAL mode, the transmitter state can be selected as shown in the Table 5. In case the over-temperature flag is set the Transmitter will be disabled. The bus wires are terminated to VCC/2 via Receiver input resistances.

Table 5. Transmitter State

| BGE | TxEN | TxD | Transmitter state | Bus State |
|-----|------|-----|-------------------|---|
| H | L | H | Enabled | Data1 (BP is driven high, BM is driven low) |
| H | L | L | Enabled | Data0 (BP is driven low, BM is driven High) |
| X | H | X | Disabled | Idle (BP and BM are not driven) |
| L | X | X | Disabled | Idle (BP and BM are not driven) |

- If the differential bus voltage is higher than $V_{BUSActiveHigh}$ or lower than $V_{BUSActiveLow}$ for a time longer than $t_{BUSActivityDetection}$, then activity is detected on the bus (Bus = active), RxEN is switched to logical "low" and RxD is released.
- If, after the activity detection, the differential bus voltage is higher than V_{Data1} , RxD is high.
- If, after the activity detection, the differential bus voltage is lower than V_{Data0} , RxD is low.
- If the absolute differential bus voltage is lower than $V_{BUSActiveHigh}$ and higher than $V_{BUSActiveLow}$ for a time longer than $t_{BUSIdleDetection}$, then idle is detected on the bus (Bus = idle), RxEN and RxD are switched to logical "high"

8.3.2 RECEIVE-ONLY Mode

In RECEIVE-ONLY mode the Transmitter is disabled but the Receiver is active.

8.3.3 STANDBY Mode

In this mode the Transceiver is not able to send and receive data signals from the bus, but the wake-up detector is active. The power consumption is significantly reduced with respect to the non-low-power operation modes. RxD and RxEN, reflects the negation of the wake-up flag. INH1 is set to high. If wake-up flag is set then INH2 is high, otherwise it is floating. The error-read-out-mechanism is not enabled. The bus wires are terminated to GND (bus state: Idle_LP).

8.3.4 GO-TO-SLEEP Mode

In this mode the Transceiver has the same behavior as in STANDBY mode but if this mode is selected for a time longer than t_{SLEEP} and the wake flag is cleared the device enters into the SLEEP mode.

8.3.5 SLEEP Mode

In SLEEP mode only the bus wake and local wake detection is enabled. IN1 and INH2 are floating.

8.4 Non Operating Mode

The AS8221 provides the following non operating mode:

8.4.1 POWER-OFF

In this mode the Transceiver is not able to operate. RxD, RxEN are set to high and ERRN is set to low. INH1 and INH2 are floating. The bus wires are not connected to GND (bus state: Idle_HZ).



8.5 Undervoltage Events

The device monitors the following three voltage supplies:

- V_{BAT}: Battery supply voltage
- V_{IO}: Supply voltage for I/O digital level adaptation
- V_{CC}: Supply voltage (+5V)

8.5.1 Undervoltage/Voltage Recovery V_{BAT}

If V_{BAT} voltage falls below V_{BATTHL} for a time longer than t_{UV_DETECT} then the undervoltage V_{BAT} flag is set and it is reset if V_{BAT} exceeds the voltage threshold V_{BATTHH} for a time longer than t_{UV_REC} or in case a wake-up event has been detected. The flag can be set or reset in all the modes.

8.5.2 Undervoltage/Voltage Recovery V_{IO}

If V_{IO} voltage falls below V_{IOthL} for a time longer than t_{UV_DETECT} then the undervoltage V_{IO} flag is set and it is reset if V_{IO} exceeds the voltage threshold V_{IOthH} for a time longer than t_{UV_REC} or in case a wake-up event has been detected. The flag can be set or reset in all the operation modes. The flag is automatically reset at POWER-OFF.

8.5.3 Undervoltage/Voltage Recovery V_{CC}

If V_{CC} voltage falls below V_{CCthL} for a time longer than t_{UV_DETECT} then the undervoltage V_{CC} flag is set and it is reset if V_{CC} exceeds the voltage threshold V_{CCthH} for a time longer than t_{UV_REC} or in case a wake-up event has been detected. The flag can be set or reset in all operation modes. The flag is automatically reset at POWER-OFF.

8.6 Power On/Off Events

- Starting from POWER-OFF mode a power on event occurs in case V_{BAT} undervoltage flag is reset.
- Starting from every operation mode a POWER-OFF event occurs in case V_{BAT} and V_{CC} undervoltage flags are set.

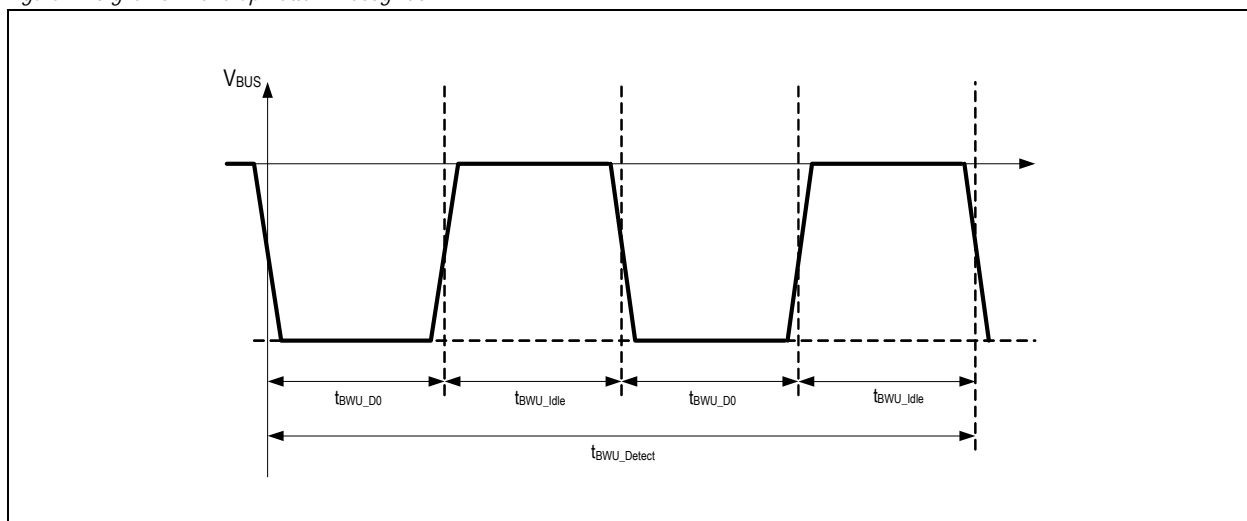
8.7 Wake-Up Events

A wake-up event can be detected only in low-power modes. The wake-up flag is set if the remote or local wake flag is set. The wake-up flag is reset if both the remote and local wake-up flags are reset. The remote wake-up flag is set if a remote wake-up event occurs. The local wake-up flag is set if a local wake-up event occurs. The remote and local wake-up flags are reset entering a low-power mode from a non-low-power mode, entering NORMAL mode, whenever an undervoltage event occurs and at POWER-OFF.

8.7.1 Remote Wake-Up Event

A remote wake-up event, only possible in low-power mode, consists in the reception of at least two consecutive wake-up symbols via the bus within t_{BWU_Detect}. The wake-up symbol is defined as Data0 longer than t_{BWU_D0} followed by idle or Data1 longer than t_{BWU_Idle} as in Figure 7 unless an undervoltage or wake-up event is present.

Figure 7. Signal for Wake-up Pattern Recognition

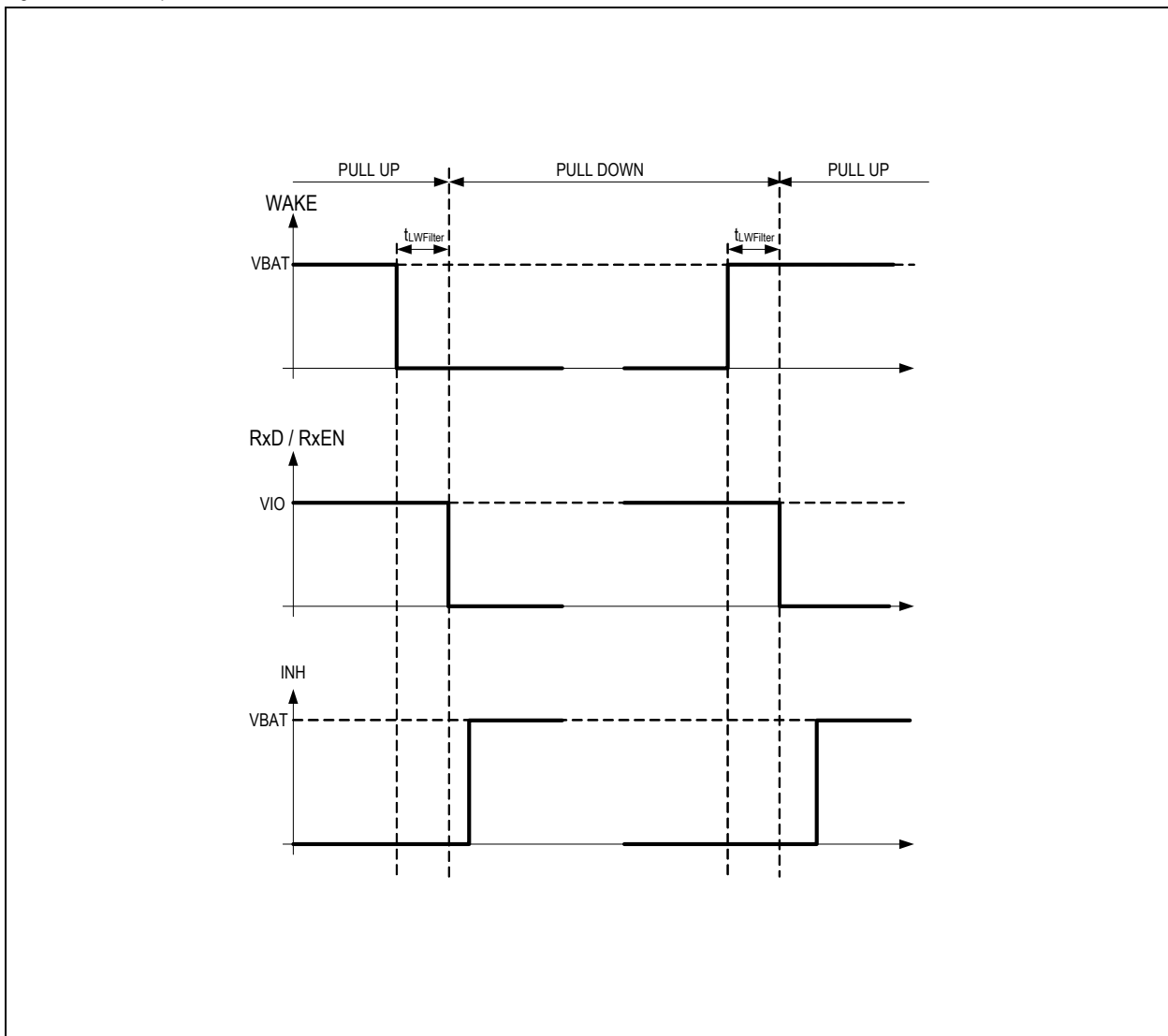




8.7.2 Local Wake-Up Event

In all low-power modes, if the voltage on the WAKE pin falls below V_{LWUTH} for longer than $t_{LWFilter}$, a local wake-up event is detected. At the same time the biasing of the pin is switched to pull-down. If the voltage on the WAKE pin rises above V_{LWUTH} for longer than $t_{LWFilter}$, a local wake-up event is detected. At the same time the biasing of the pin is switched to pull-up. The pull up and down mechanism is active in low-power and non-low-power modes.

Figure 8. WAKE Input Pin Behavior

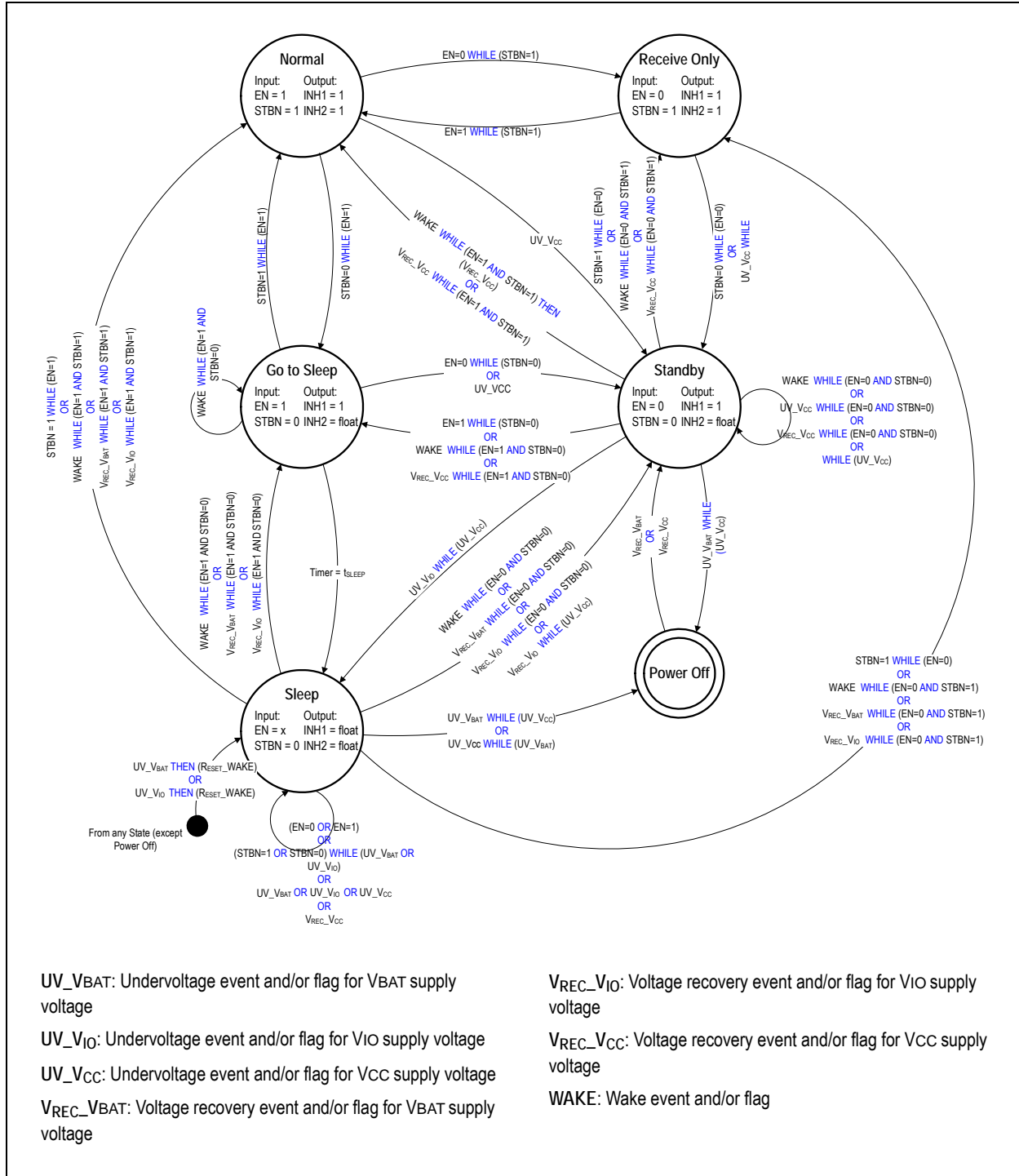




9 Application Information

System Description. Note that the state diagram does not include all the transitions described in Table 7.

Figure 9. State Diagram



Prefix of "WHILE" is an event and suffix in brackets checks the flags or in case of EN and STBN the input condition. For example: VREC_VBAT WHILE (EN=0 AND STBN=0).

After the event VBAT supply voltage recovery is detected, the transition is performed if EN and STBN are "low".



9.1 Fail Silent Behavior

9.1.1 RxEN / BGE timeout

In case no edges on RxEN and BGE within $t_{TxEN_timeout}$ are detected, the transmitter will stop transmitting the signals on RxD to the bus pins.

9.1.2 State Transitions due to Undervoltage Detection

- In case of VBAT or VIO undervoltage is detected, SLEEP mode will be entered regardless the status of EN and STBN.
- In case VCC undervoltage is detected, STANDBY mode will be entered regardless the status of EN and STBN.
- VBAT and VIO undervoltage detection have higher priority than VCC undervoltage detection.
- In case undervoltage at VBAT and VCC is detected, POWER-OFF mode is entered (bus state: Idle_HZ).

9.1.3 State Transitions due to Voltage Recovery Detection

- If the voltage recovers the device will enter the mode selected by the EN and STBN pins, in case no undervoltage is present at the other supply pins.
- Starting from the POWER-OFF, the device enters the state selected by the host input pins (EN, STBN) only if VBAT or VCC recovers ($V_{BAT} \geq V_{BATTHH}$ or $V_{CC} \geq V_{CCTHH}$) while VIO is available (undervoltage flag of VIO flag not set). If the VIO undervoltage flag is set, the STANDBY mode will be entered. In both cases the Power-On flag is set.
- If $V_{BAT} \leq V_{BATLH}$ and $V_{CC} \leq V_{CCTLH}$ the device will be in POWER-OFF state, thus the bus wires are not terminated (bus state: Idle_HZ).

9.2 Mode Transitions

In case of power-off event, the device enters POWER-OFF regardless VIO undervoltage flag, wake-up flags and regardless the selection at the host input pins.

Starting from the POWER-OFF the device enters STANDBY only in case a power on event occurs.

Starting from every operating mode the device enters SLEEP in case VBAT or VIO undervoltage flag is set regardless the VCC undervoltage flag, the wake-up flag and the state of the host input pins.

Starting from every operating mode except SLEEP the device enters STANDBY in case VCC undervoltage flag is set and VBAT and VIO undervoltage flags are not set, regardless the wake-up flag indication and the host input pins state.

Starting from a low-power mode the device enters the operation mode indicated by the host input pins if a wake-up event occurs.

In case all the undervoltage flags are reset the operation mode is selected by the wake-up flag and the host pins according to [Table 6](#).

Table 6. Pin Signalling and Operating Modes

| Inputs | | Operation Mode | Output | | | | |
|--------|----|----------------|---------------------------|--------------------|--------------------|----------|----------|
| STBN | EN | | RxD | ERRN | RxEN | INH1 | INH2 |
| H | H | NORMAL | L Bus = Data_0 | NOT [Error flag] | L Bus = Active | H | H |
| | | | H Bus = Idle or Data_1 | | H Bus = Idle | | |
| H | L | RECEIVE-ONLY | L Bus = Data_0 | NOT [Error flag] | L Bus = Active | H | H |
| | | | H Bus = Idle or Data_1 | | H Bus = Idle | | |
| L | H | GO-TO-SLEEP | NOT [Wake-up flag] | NOT [Wake-up flag] | NOT [Wake-up flag] | H | Floating |
| L | L | STANDBY | NOT [Wake-up flag] | NOT [Wake-up flag] | NOT [Wake-up flag] | H | Floating |
| L | X | SLEEP | NOT [Wake-up flag] | NOT [Wake-up flag] | NOT [Wake-up flag] | Floating | Floating |
| X | X | POWER-OFF | H | L | H | Floating | Floating |

Where: H = Digital level high, L = Digital level low, X = Do not care!, Floating = The analog output is not driven.

**Notes:**

1. If GO-TO-SLEEP is selected for more than t_{SLEEP} then the device will enter SLEEP only if the wake-up flag is not set otherwise it will remain in GO-TO-SLEEP.
2. If wake-up flag is set INH2=H otherwise INH2=floating.
3. Starting from SLEEP, if the wake-up flag is set, the device enters STANDBY regardless the host pins state and UV flags. Starting from SLEEP, if the wake-up flag is not set, the only operating mode that can be entered through host pins are the non-low-power modes.

9.2.1 Operating Mode Transitions

Table 7. Transition Table

| Transition | | Event | Under Voltage Flag | | | Wake Flag | Host Input | | Remarks | |
|--------------|--------------|-------|--------------------|------------------|-----------------|-----------|------------|---------|---------------------|----------------------|
| Start Point | Destination | | V _{IO} | V _{BAT} | V _{CC} | | STBN | EN | | |
| NORMAL | RECEIVE-ONLY | S | L | L | L | X | H | (1) H→L | | |
| | STANDBY | U | L | L | (1) L→H | (2) X→L | H | H | | |
| | GO-TO-SLEEP | S | L | L | L | (2) X→L | (1) H→L | H | sleep timer enabled | |
| | SLEEP | U | (1) L→H | L | L | (2) X→L | H | H | | |
| L | | | (1) L→H | | (2) X→L | H | H | | | |
| RECEIVE-ONLY | NORMAL | S | L | L | L | X | H | (1) L→H | | |
| | STANDBY | S | L | L | L | (2) X→L | (1) H→L | L | | |
| | | U | L | L | (1) L→H | (2) X→L | H | L | | |
| | SLEEP | U | (1) L→H | L | L | (2) X→L | H | L | | |
| U | | L | (1) L→H | L | (2) X→L | H | L | | | |
| STANDBY | NORMAL | U | L | L | (1) H→L | L | H | H | | |
| | | W | L | L | (2) H→L | (1) L→H | H | H | | |
| | RECEIVE-ONLY | S | L | L | L | X | (1) L→H | L | | |
| | | U | L | L | (1) H→L | L | H | L | | |
| | GO-TO-SLEEP | W | L | L | (2) H→L | (1) L→H | H | L | | |
| | | S | L | L | L | L | L | L | (1) L→H | sleep timer enabled |
| | | S | L | L | L | L | H | L | (1) L→H | sleep timer disabled |
| | | U | L | L | (1) H→L | L | L | H | | sleep timer enabled |
| | SLEEP | W | L | L | (2) H→L | (1) L→H | L | H | | sleep timer disabled |
| | | U | (1) L→H | L | L | (2) X→L | L | L | | |
| | | U | (1) L→H | L | H | L | X | X | | |
| | | U | L | (1) L→H | L | (2) X→L | L | L | | |
| | STANDBY | W | L | L | (2) X→L | (1) L→H | L | L | | |
| | | U | L | L | (1) L→H | (2) X→L | L | L | | |
| | | U | L | L | (1) H→L | L | L | L | | |
| | | S | L | L | H | L | (1) L↔H | X | | |
| S | L | L | H | L | L | X | (1) L↔H | | | |



Table 7. Transition Table

| Transition | | Event | Under Voltage Flag | | | Wake Flag | Host Input | | Remarks | |
|-------------|--------------|-------|--------------------|------------------|-----------------|-----------|------------|----------------------|----------------------|--------------------|
| Start Point | Destination | | V _{IO} | V _{BAT} | V _{CC} | | STBN | EN | | |
| GO-TO-SLEEP | NORMAL | S | L | L | L | X | (1) L→H | H | | |
| | STANDBY | S | L | L | L | X | L | (1) H→L | | |
| | | U | L | L | (1) L→H | (2) X→L | L | H | | |
| | SLEEP | S | L | L | L | L | L | L | H | t_{SLEEP} |
| | | U | (1) L→H | L | L | (2) X→L | L | L | H | |
| | | U | L | (1) L→H | L | (2) X→L | L | L | H | |
| GO-TO-SLEEP | W | L | L | L | (1) L→H | L | H | sleep timer disabled | | |
| SLEEP | NORMAL | S | L | L | L | L | (1) L→H | H | | |
| | | W | (2) X→L | (2) X→L | (2) X→L | (1) L→H | H | H | | |
| | | U | L | (1) H→L | L | L | H | H | | |
| | | U | (1) H→L | L | L | L | H | H | | |
| | RECEIVE-ONLY | S | L | L | L | L | (1) L→H | L | | |
| | | W | (2) X→L | (2) X→L | (2) X→L | (1) L→H | H | H | | |
| | | U | L | (1) H→L | L | L | H | L | | |
| | | U | (1) H→L | L | L | L | H | L | | |
| | STANDBY | W | (2) X→L | (2) X→L | (2) X→L | (1) L→H | L | L | | |
| | | U | L | (1) H→L | L | L | L | L | | |
| | | U | (1) H→L | L | L | L | L | L | | |
| | | U | (1) H→L | L | H | L | X | X | | |
| | GO-TO-SLEEP | W | (2) X→L | (2) X→L | (2) X→L | (1) L→H | L | H | sleep timer disabled | |
| | | U | L | (1) H→L | L | L | L | H | sleep timer disabled | |
| | | U | (1) H→L | L | L | L | L | H | sleep timer disabled | |
| | SLEEP | S | X | X | X | L | X | (1) L↔H | | |
| | | S | H | L | X | L | (1) L↔H | X | | |
| | | S | L | H | L | L | (1) L↔H | X | | |
| | | S | H | H | L | L | (1) L↔H | X | | |
| | | U | X | (1) L→H | L | L | X | X | | |
| | | U | (1) L→H | X | X | L | X | X | | |
| U | | L | L | (1) L↔H | L | X | X | | | |

Note: S = transition forced via EN, STBN; U = transition forced via undervoltage or voltage recovery; W = transition forced via WAKE

(1) Indicates the action, that initiates the transition

(2) Indicates the consequence after performed transition

(3) In case the wake flag is set, it is not possible to enter SLEEP mode through a Sleep command, requested by the host.

(4) In case an undervoltage on V_{BAT} and V_{CC} is detected, the device enters the POWER-OFF state.



9.2.2 ERRN Signalling

The ERRN signalling is shown in Table 8.

Table 8. ERRN Signalling

| Supply Voltage Flag Event V_{IO} | RWAKE Flag | LWAKE Flag | Host Command | | ERRN |
|---------------------------------------|------------|------------|--------------|----|--|
| | | | STBN | EN | |
| L | X | X | H | H | NOT [error flag] |
| L | H | X | H | L | If rising edge at EN, then NOT [error flag] else L |
| L | L | X | H | L | If rising edge at EN, then NOT [error flag] else H |
| L | L | L | L | X | H |
| L | L | L→H | L | X | H→L |
| L | L→H | L | L | X | H→L |
| L | H | L→H | L | X | L |
| L | L→H | H | L | X | L |
| H | X | X | X | X | L |

9.3 Loss of Ground

Whenever a loss of ground is detected, the bus lines are switched Idle_HZ with the precondition that the host pins are open. Either error or no error can be indicated on the ERRN pin.

9.4 Error Flags

9.4.1 Undervoltage

- **UVVBAT_DET**: The VBAT undervoltage flag is set if the VBAT voltage falls below V_{BATTHL} for longer than t_{UV_DETECT} and is reset if the VBAT voltage reaches a voltage level higher than V_{BATTHH} for longer than t_{UV_DETECT} .
- **UVVIO_DET**: The VIO undervoltage flag is set if the VCC voltage falls below V_{CCTHL} for longer than t_{UV_DETECT} and is reset if the VCC voltage reaches a voltage level for longer than V_{CCTHH} after t_{UV_DETECT} .
- **UVVCC_DET**: The VCC undervoltage flag is set if the VIO voltage falls below V_{IOTHL} for longer than t_{UV_DETECT} and is reset if the VIO voltage reaches a voltage level higher than V_{IOTHH} for longer than t_{UV_DETECT} .

9.4.2 Bus Error (BUSERR)

The bus error flag is set if 2 consecutive rising edges on the TxD pin without any rising edge on the RxD pin are detected or if 2 consecutive falling edges on the TxD pin without any falling edge on the RxD pin are detected. This flag is reset if a rising edge on the TxD pin is followed by a rising edge on RxD pin before the next TxD rising edge or if a falling edge on the TxD pin is followed by a falling edge on RxD pin before the next TxD falling edge. This flag can be set or reset only in NORMAL mode when the transmitter is enabled. The flag is reset at POWER-OFF.

9.4.3 Short Circuit between BP and BM (BP_BM)

The BP_BM can only be set or reset in NORMAL mode while the driver is active (edge at TxEN) for a time longer than t_{BUS_ERROR} .

The flag is set if the absolute value of the differential voltage is lower than V_{SHORT} for a time t_{BUS_ERROR} .

The flag is reset in POWER-OFF mode and if the set condition is not fulfilled.

9.4.4 Over Temperature (OT)

This flag can only be set or reset in the non-low-power modes. The flag is set if the junction temperature exceeds OT_{TH} and it is reset if the junction temperature falls below OT_{TL} .

9.4.5 TxEN_BGE Timeout (TxEN_TO)

This flag can only be set in NORMAL mode if the driver is enabled (TxEN is low and BGE is high) for a time longer than t_{TxEN_max} . It is reset during transition on TxEN or BGE or if the device exits NORMAL mode. If the flag is set the driver is disabled.



9.4.6 Error Flag (ERROR)

The ERROR is signalled on the ERRN pin according to [Table 6](#) and [Table 8](#).

The flag is set if at least one of the error flags in chapters [9.4.2](#) to [9.4.5](#) is set. The flag will be reset if none of the flags in chapters [9.4.2](#) to [9.4.5](#) is set.

9.5 Status Flags

9.5.1 Local Wake Flag (LWAKE)

See chapter [8.7 Wake-Up Events on page 16](#)

9.5.2 Remote Wake Flag (RWAKE)

see chapter [8.7 Wake-Up Events on page 16](#)

9.5.3 Power on Flag (PWON)

The PWON is set leaving the POWER-OFF state and it is reset entering a low-power mode after a non-low-power mode.

9.6 Error Flags and Status Flags Read-Out

The readout mechanism consists of two information groups:

1. Error read-out
2. Status information read-out

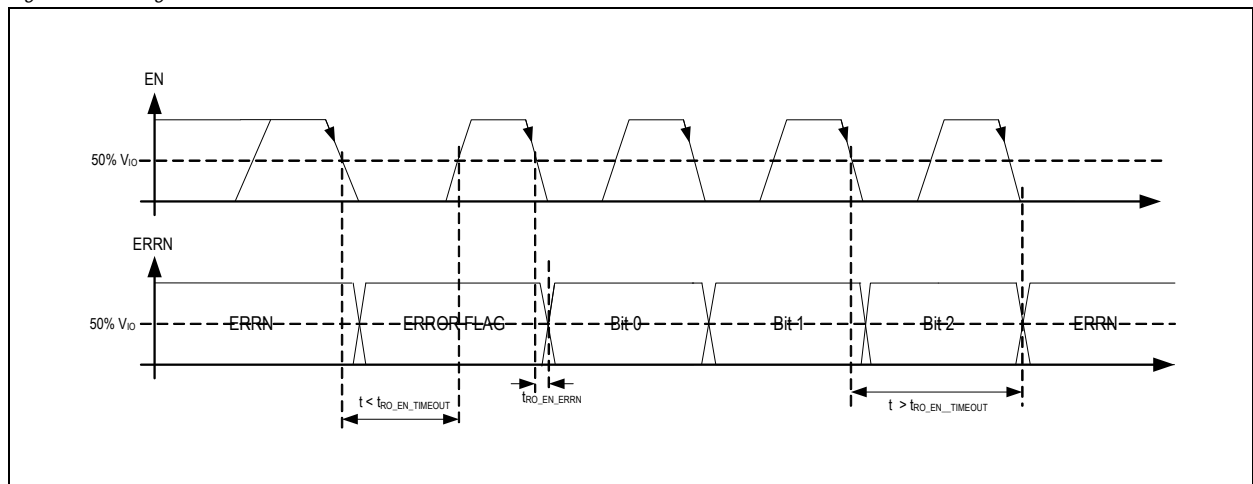
The read-out mechanism as serial transmission on Pin EN and ERRN:

Table 9. Read-out Mechanism and Transceiver States

| State | Enabled / Disabled |
|-------------------|--------------------|
| NORMAL mode | Enabled |
| RECEIVE-ONLY mode | Enabled |
| STANDBY mode | Disabled |
| GO-TO-SLEEP mode | Disabled |
| SLEEP mode | Disabled |

The error flags and the status flags can be read-out by applying a clock signal to pin EN in a non-low-power mode. A falling edge on pin EN starts the read-out loading the content of the error/status flag into the shift register and signaling the error flag on the ERRN pin. On the second falling edge the first flag (Bit 0) will be shifted out. The ERRN data is valid after $t_{RO_EN_ERRN}$. If EN pin keeps on toggling after the last flag (Bit 15) the next flag again is Bit 0. The complete list of bits is shown in [Table 10](#). If no transition is detected on pin EN for longer than $t_{RO_EN_TIMEOUT}$ the device enters the operation mode selected by the host pins.

Figure 10. Timing of the Read-out Mechanism





9.6.1 Error and Status Flag Bit Order

Table 10. Bit Order for the Read-out Sequence

| Bit | Description | Symbol |
|--------|---------------------------------|-------------------------|
| Bit 0 | Undervoltage VBAT detected | UVV _{BAT} _DET |
| Bit 1 | Undervoltage VIO detected | UVV _{IO} _DET |
| Bit 2 | Undervoltage VCC detected | UVV _{CC} _DET |
| Bit 3 | Bus error | BUSERR |
| Bit 4 | Reserved | Reserved |
| Bit 5 | | |
| Bit 6 | | |
| Bit 7 | | |
| Bit 8 | | |
| Bit 9 | | |
| Bit 10 | Short circuit between BP and BM | BP_BM |
| Bit 11 | Over temperature | OT |
| Bit 12 | TxEN_BGE timeout | TxEN_TO |
| Bit 13 | Local wake flag | LWAKE |
| Bit 14 | Remote wake flag | RWAKE |
| Bit 15 | Power on flag | PWON |

When the read-out mechanism is started, the first data information is the Bit 0 until Bit 15 is transmitted. Any re-initiation or repetitions is started with the first data Bit 0.

9.7 Bus Driver

9.7.1 Bus States

Activity: The bus wires reflects the differential signal specified in chapter 9.9 Transmitter on page 26.

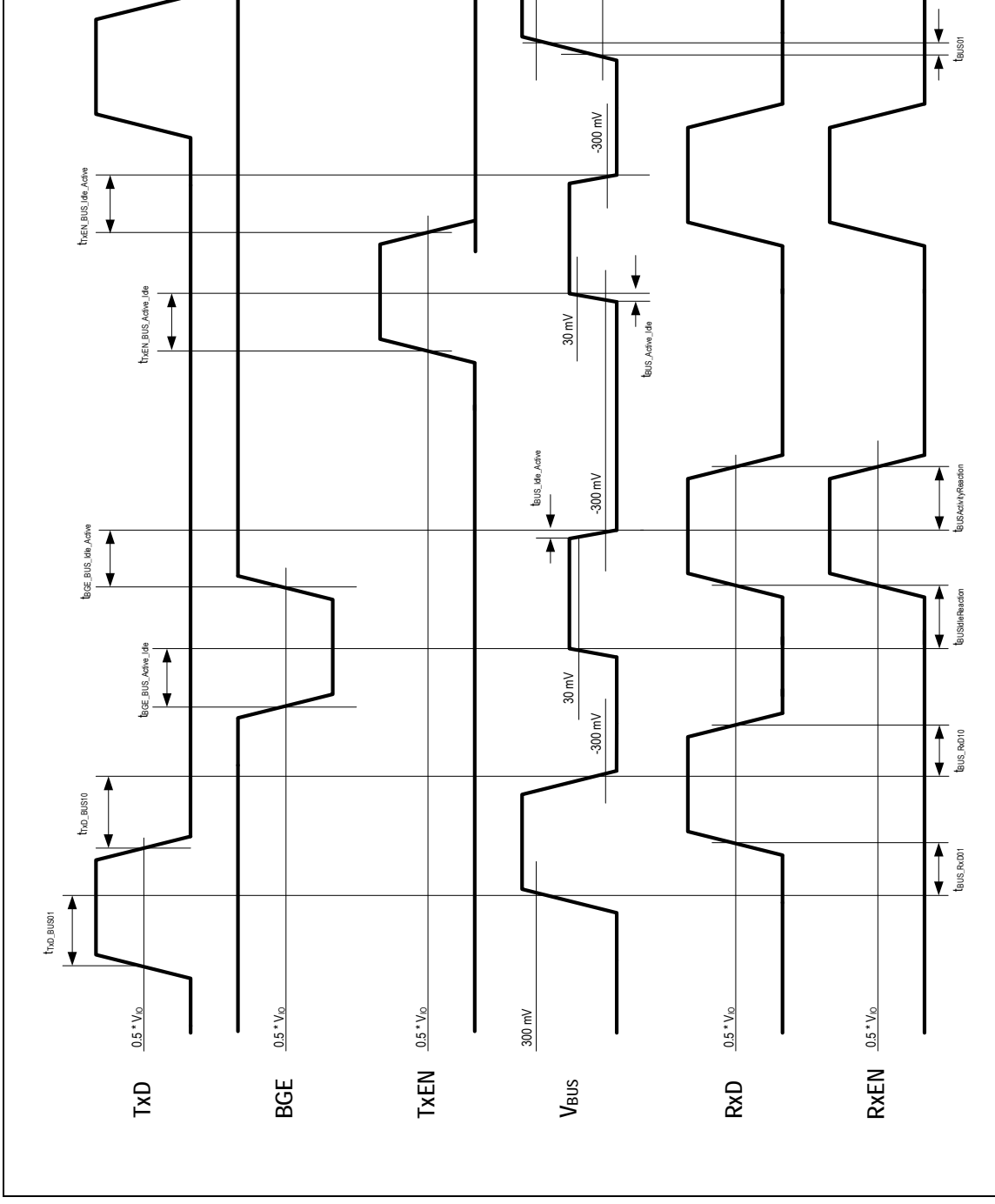
Idle: The bus wires are terminated to V_{CC}/2 via receiver input resistances.

Idle_LP: The bus wires are terminated to GND via receiver input resistances.

Idle_HZ: The bus wires are not terminated to V_{CC}/2 via 1MΩ

9.8 Transceiver Timing

Figure 11. Timing Diagram





9.9 Transmitter

The transmitter generates out of a digital input signal on TxD the FlexRay differential bus voltage. The transmitter is only active in NORMAL mode if BGE is on logical high and TxEN is on logical low.

Figure 12. Transmitter Characteristics (TxD → BUS)

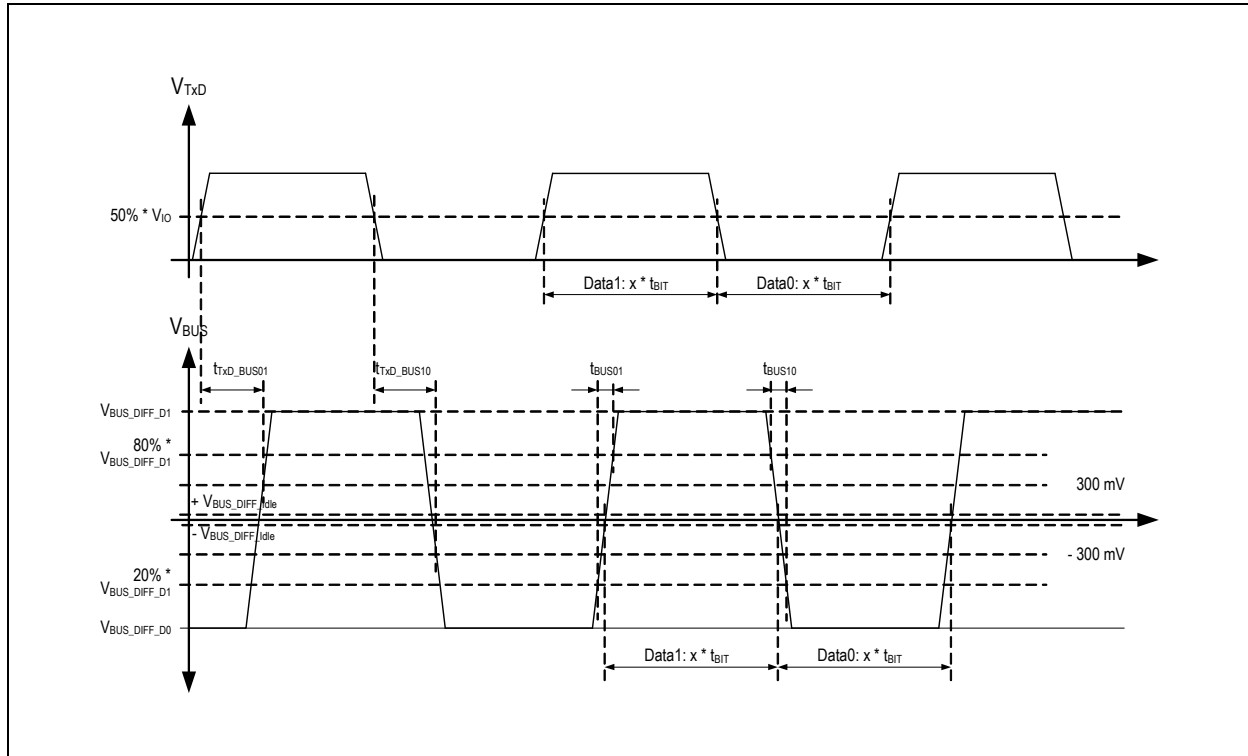


Figure 13. Transmitter Characteristics (TxEN → BUS)

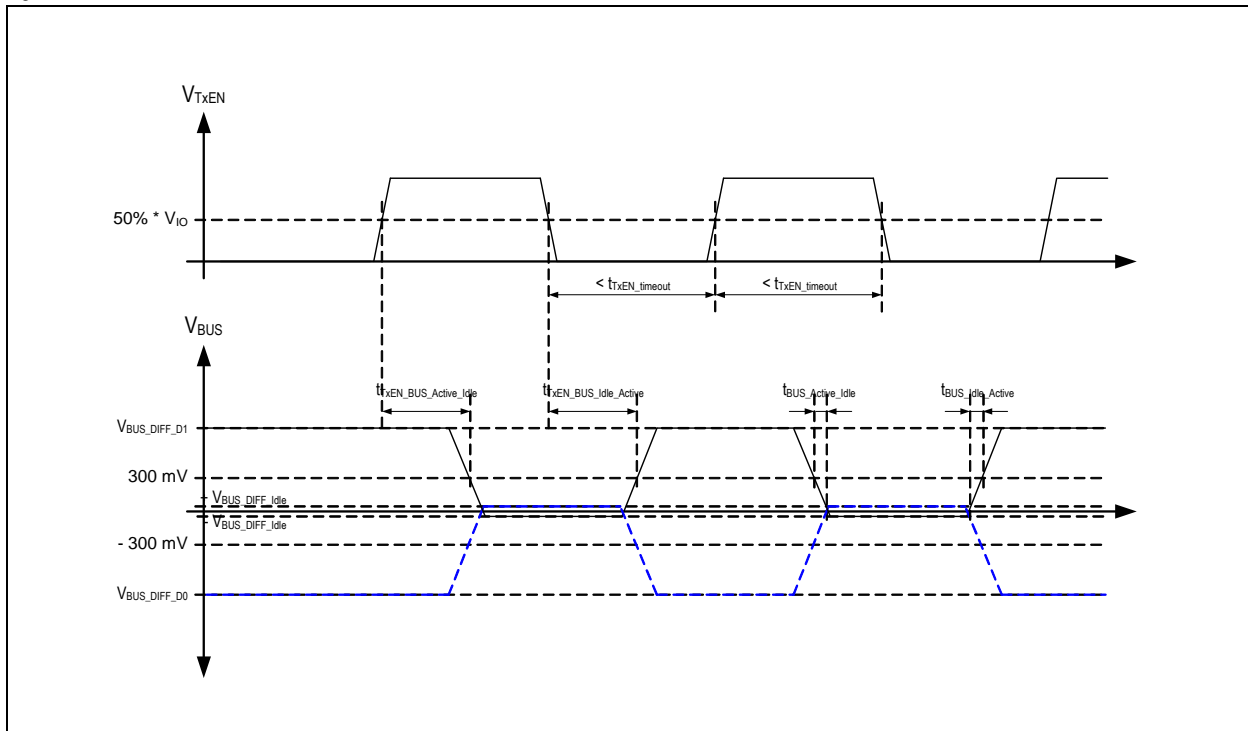
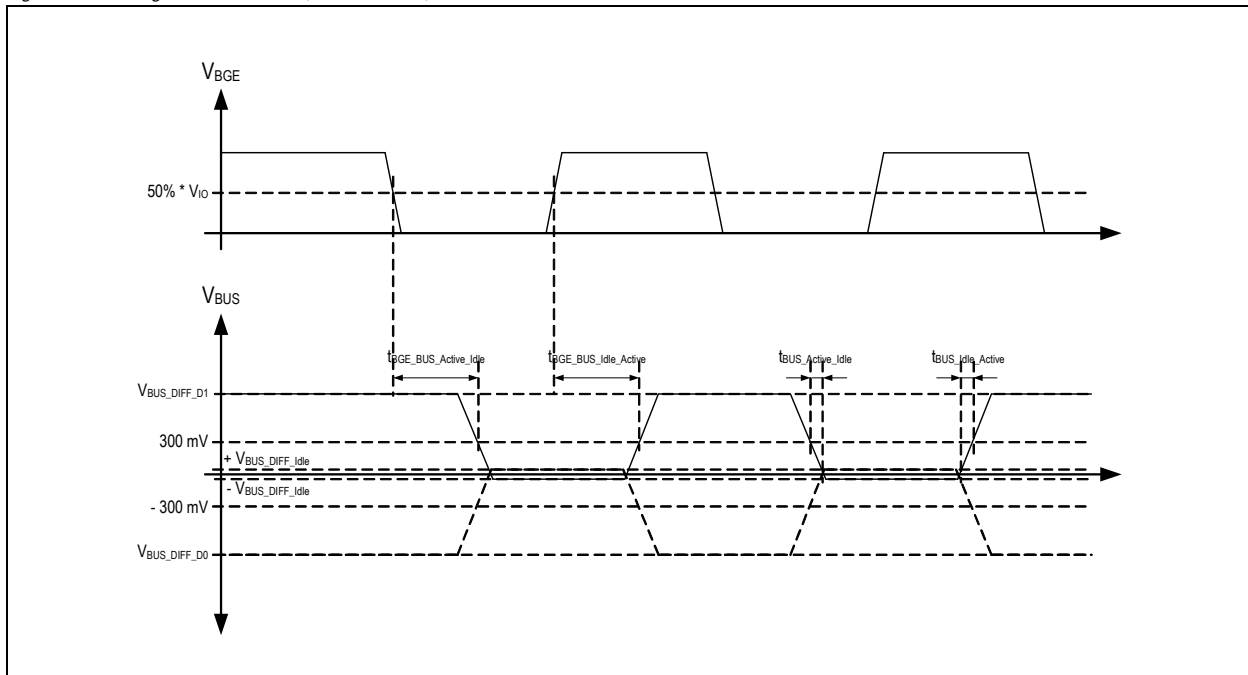




Figure 14. Timing Characteristics (BGE → BUS)

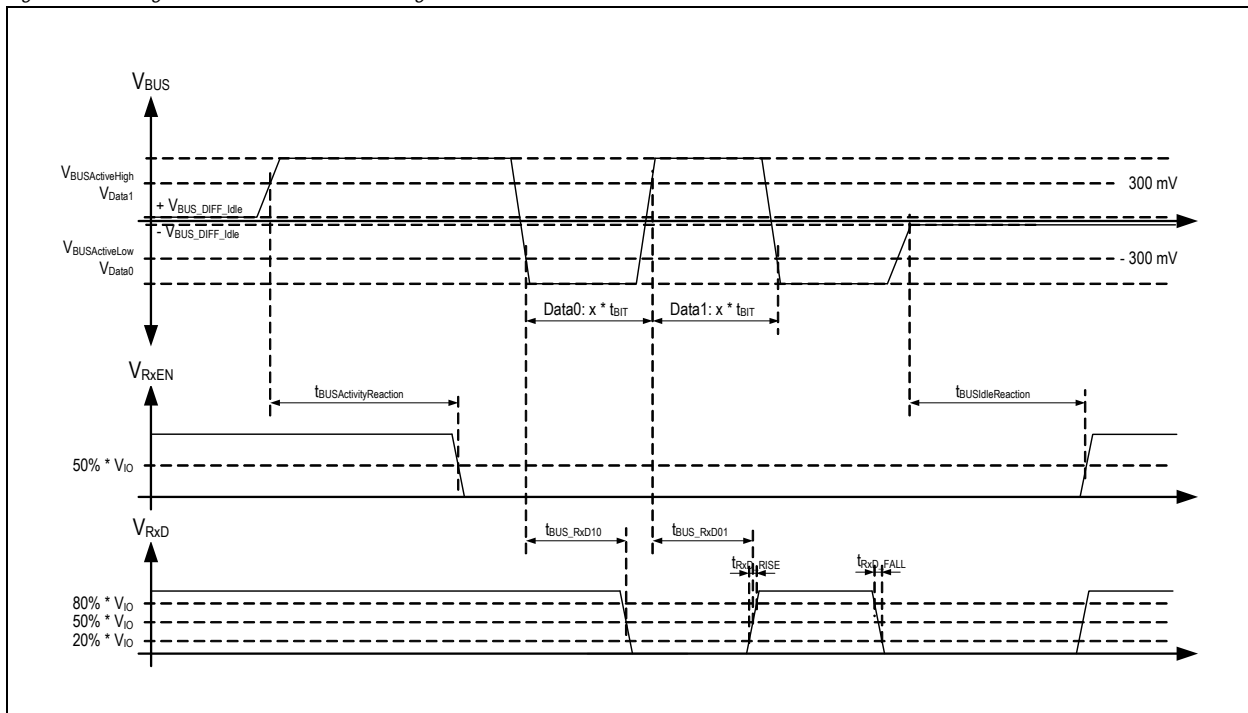


In NORMAL and RECEIVE-ONLY mode, the transmitter drives on the bus Idle in case no data are transmitted. In STANDBY, GO-TO-SLEEP and SLEEP mode the transmitter drives Idle_LP on the bus pins. In POWER-OFF mode the bus pins shows Idle_HZ.

9.10 Receiver

The Receiver generates from the FlexRay differential bus voltage a digital signal on the RxD and RxEN pins. RxD shows the data (Data0 and Data1) and RxEN shows the bus idle and activity status received on the bus pins. The Receiver is only active in NORMAL and RECEIVE-ONLY mode.

Figure 15. Timing Characteristics of the Bus Signals to RxD and RxEN





9.10.1 Bus Activity and Idle Detection (only in NORMAL and RECEIVE-ONLY mode)

If the absolute differential bus voltage is higher than $V_{BUSActiveLow}$ and less than $V_{BUSActiveHigh}$ for a time longer than $t_{BUSIdleDetection}$, bus Idle is detected, RxEN and RxD are switched to logical high after a time $t_{BUSIdleReaction}$.

If the absolute differential bus voltage is higher than $V_{BUSActiveHigh}$ or lower than $V_{BUSActiveLow}$ for a time longer than $t_{BUSActivityDetection}$, bus Activity is detected, RxEN is switched to logical low and RxD shows the detected bus data according to Table 11 after the time $t_{BUSActivityReaction}$.

Table 11. Logic Table for Receiver Bus Signal Detection

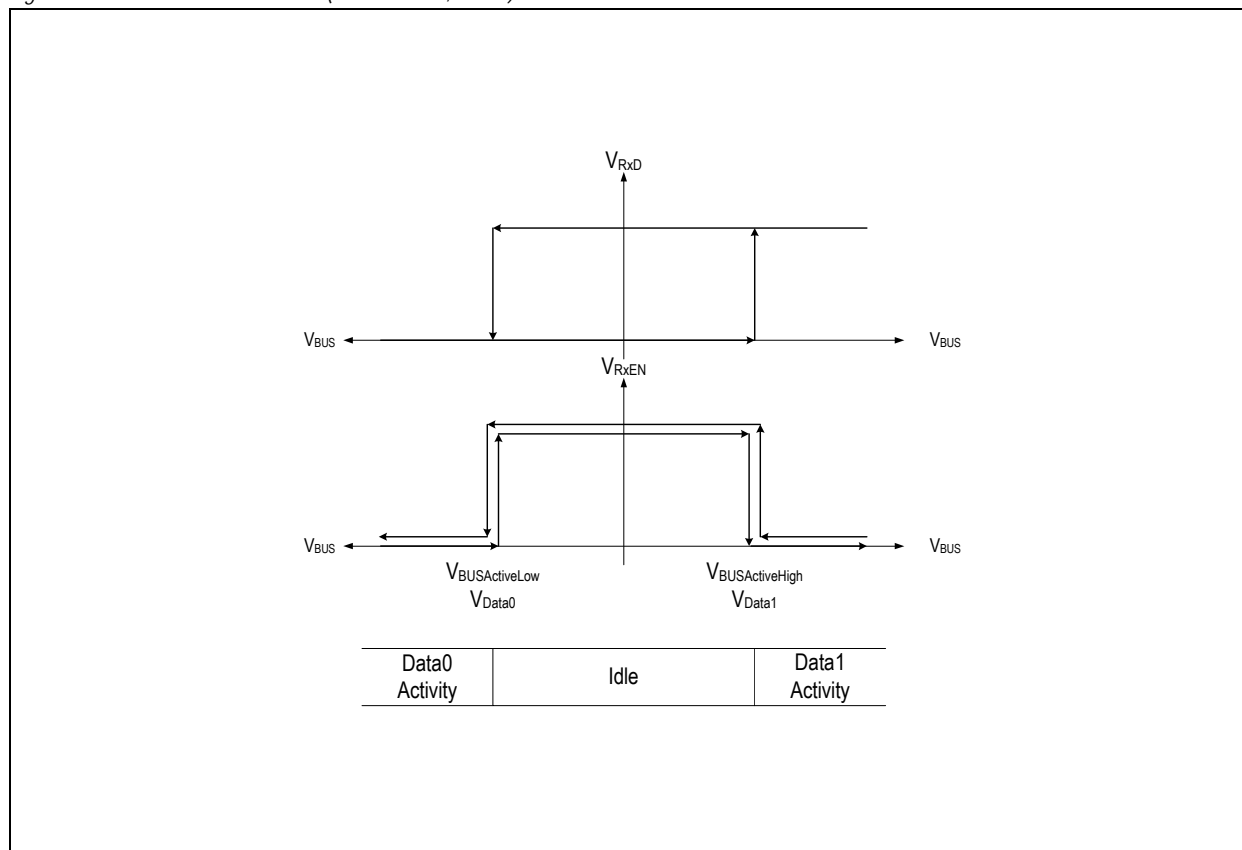
| Receiver Operation Mode | Bus Signals | RxEN | RxD |
|--|-------------|------|-----|
| Normal power modes (NORMAL and RECEIVE-ONLY mode) | Idle | H | H |
| | Data0 | L | L |
| | Data1 | L | H |

9.10.2 Bus Data Detection (only in NORMAL and RECEIVE-ONLY mode)

If, after activity detection the differential bus voltage is higher than V_{Data1} , RxD will be high after a time t_{BUS_RxD01} .

If, after activity detection the differential bus voltage is lower than V_{Data0} , RxD will be low after a time t_{BUS_RxD10} .

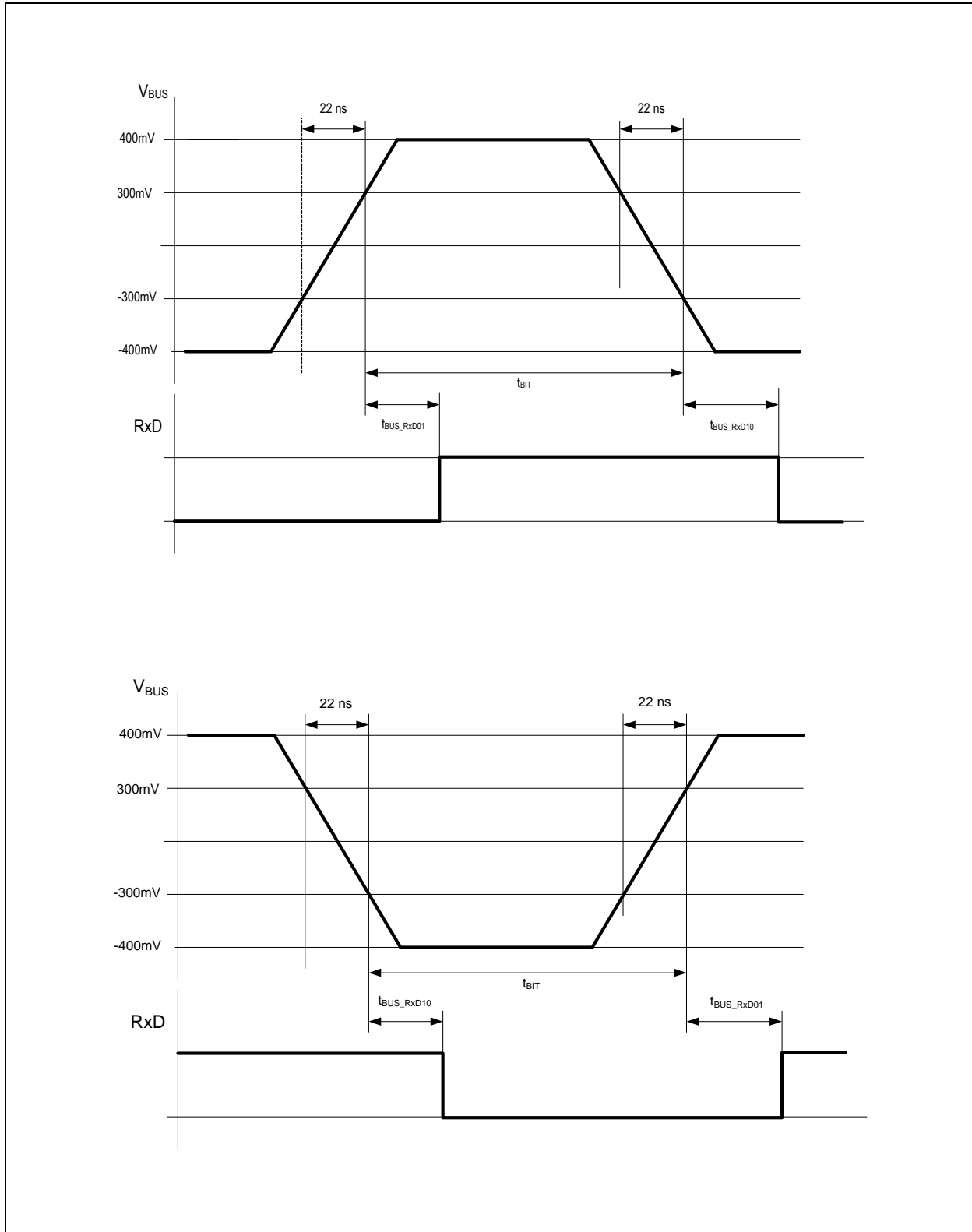
Figure 16. Receiver Characteristics (BUS → RxD, RxEN)





9.10.3 Receiver Test Signal

Figure 17. Receiver Test Signal





9.11 Test Circuits

Figure 18. Test Circuit for Automotive Transients

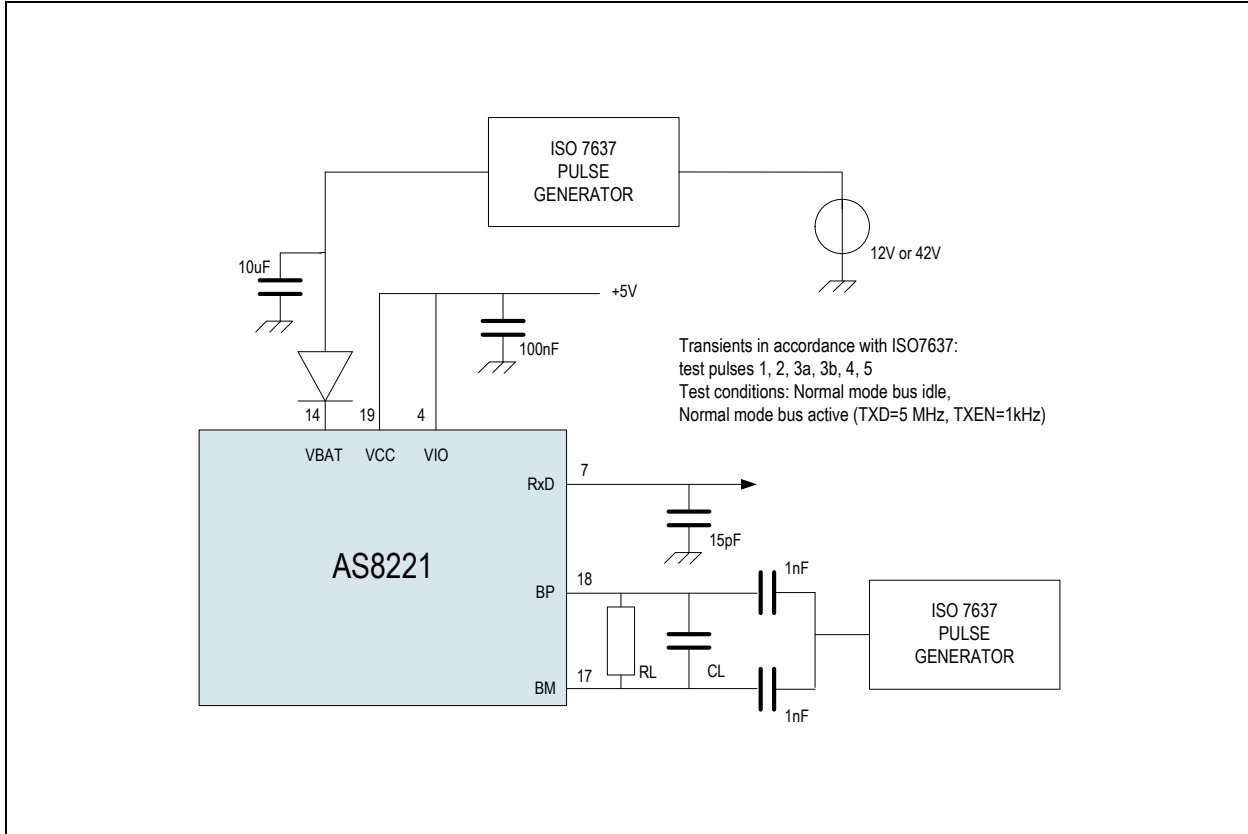
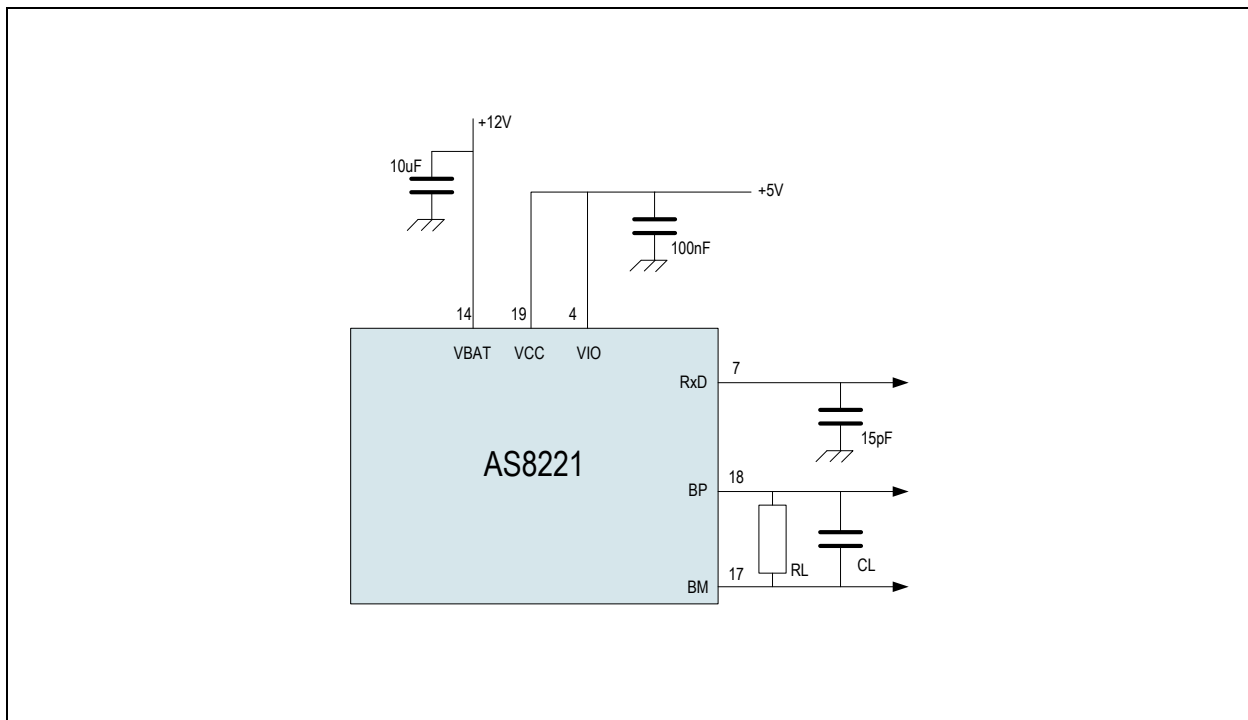
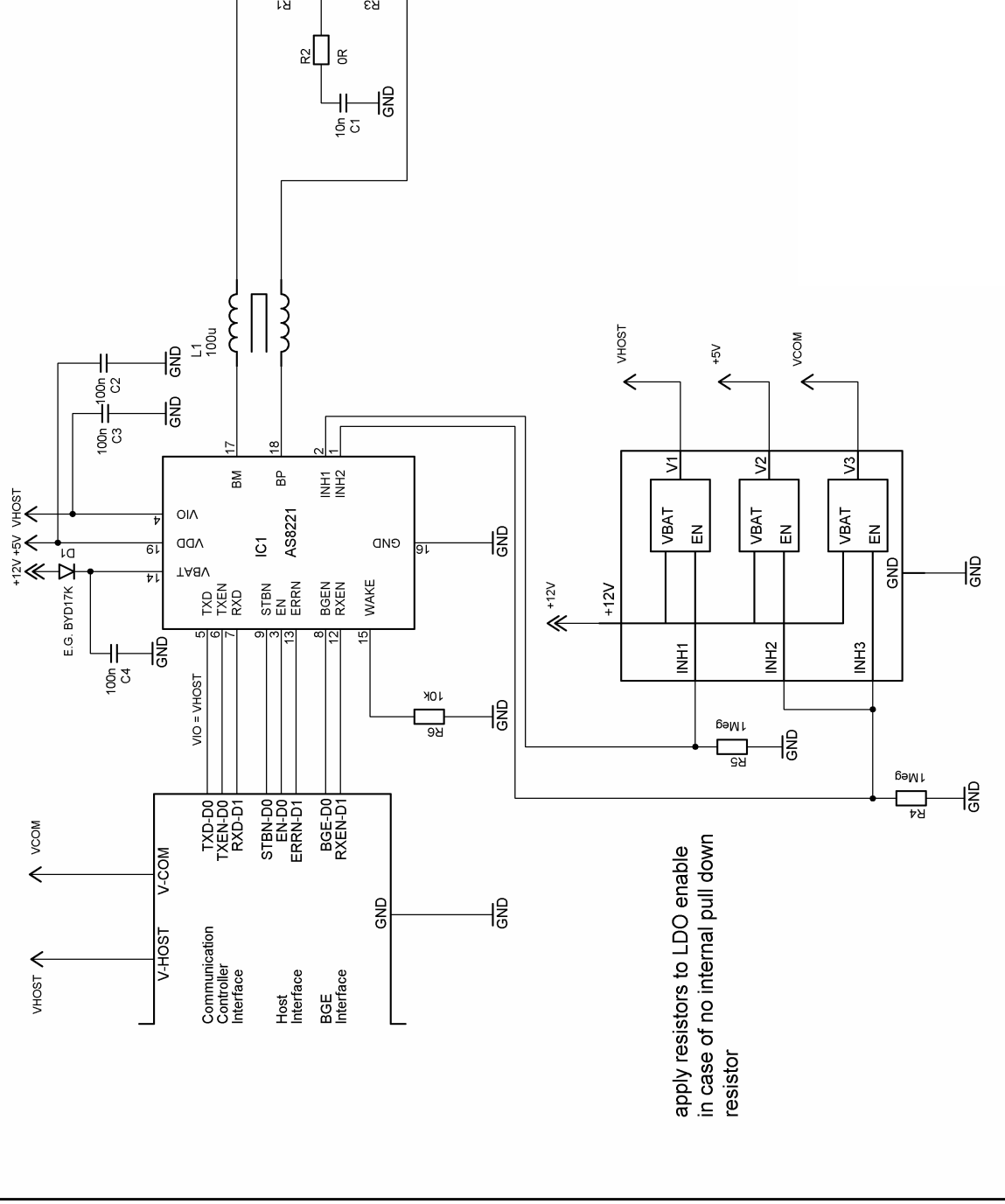


Figure 19. Test Circuit for Dynamic Characteristics



9.12 Application Circuits

Figure 20. AS8221 Application Schematic





10 Appendix

10.1 FlexRay Functional Classes

The AS8221 FlexRay Standard Transceiver has the following Bus Driver functional classes according the FlexRay Electrical Physical Layer Specification V2.1 Rev. B implemented:

- Functional Class: Chapter 8.13.1 "Bus Driver voltage regulator control"
- Functional Class: Chapter 8.13.2 "Bus Driver - Bus Guardian interface"
- Functional Class: Chapter 8.13.4 "Bus Driver logic level adaptation"

10.2 FlexRay Parameter Comparison

The following table shows the comparison of conventions used in AS8221 datasheet and FlexRay Electrical Physical Layer Specification V2.1 Rev. B.

Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|---------------------------------|---|--|--|
| Symbol | Parameter | Name | Description |
| Absolute Maximum Ratings | | | |
| - | Battery Supply Voltage (VBAT) | - | - |
| - | Supply Voltage (VCC) | - | - |
| - | Supply Voltage (VIO) | - | - |
| - | DC Voltage at EN, STBN, ERRN, TxD, RxD, TxEN, BGE, RxEN | - | - |
| - | DC Voltage on pin WAKE, INH1, INH2 | - | - |
| - | DC Voltage at BP and BM | - | - |
| - | Input current (latchup immunity) | - | - |
| - | Electrostatic discharge at bus lines BP, BM, VBAT, WAKE | uESDExt | ESD protection on pins that lead to ECU external terminals |
| - | Electrostatic discharge | uESDint | ESD on all other pins |
| - | Transient voltage on BP, BM | - | - |
| - | Transient voltage on VBAT | - | - |
| - | Total power dissipation (all supplies and outputs) | - | - |
| - | Storage temperature | - | - |
| - | Junction temperature | - | - |
| - | Package body temperature | - | - |
| - | Humidity non-condensing | - | - |
| Supply Voltage | | | |
| TAMB | Ambient temperature | T | Ambient temperature |
| VCC - VIO | Difference of supplies | - | - |
| IBAT | VBAT current consumption | - | - |
| ICC | VCC current consumption | - | - |



Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|--|--|--|---|
| Symbol | Parameter | Name | Description |
| I _{IO} | V _{IO} current consumption | - | - |
| State Transitions | | | |
| t _{STBN_RxD} | Delay STBN high to RxD high with wake flag set | - | - |
| t _{STBN_RxEN} | Delay STBN high to RxEN high with wake flag set | - | - |
| t _{SLEEP_INH1} | Delay STBN high to INH1 high | - | - |
| t _{STANDBY_INH2} | Delay STBN high to INH2 high | - | - |
| t _{SLEEP} | GO-TO-SLEEP hold time | - | - |
| Transmitter | | | |
| V _{BUS_DIFF_D0} | Differential bus voltage low in NORMAL mode (Data0) | uBDT _{xactive} | Absolute value of uBus while sending |
| V _{BUS_DIFF_D1} | Differential bus voltage high in NORMAL mode (Data1) | uBDT _{xactive} | Absolute value of uBus while sending |
| V _{BUS_DIFF} | Matching between Data0 and Data1 differential bus voltage in NORMAL mode | - | - |
| V _{BUS_COM_D0} | Common mode bus voltage in case of Data0 in non-low-power modes | - | - |
| V _{BUS_COM_D1} | Common mode bus voltage in case of Data1 in non-low-power modes | - | - |
| ΔV _{BUS_COM} | Matching between Data0 and Data1 common mode voltage | - | - |
| V _{BUS_DIFF_Idle} | Absolute differential bus voltage in idle mode | uBDT _{xidle} | Absolute value of uBus, while Idle |
| IBP _{BMSHORTMax} IBM _{BPSHORTMax} | Absolute maximum current when BP is shorted to BM | IBP _{BMSHORTMax} IBM _{BPSHORTMax} | Absolute maximum output current when BP shorted to BM |
| IBP _{GNDSHORTMax} | Absolute maximum current when BP is shorted to GND | IBP _{GNDSHORTMax} | Absolute maximum output current when shorted to GND |
| IBM _{GNDSHORTMax} | Absolute maximum current when BM is shorted to GND | IBM _{GNDSHORTMax} | Absolute maximum output current when shorted to GND |
| IBP _{-5VSHORTMax} | Absolute maximum current when BP is shorted to -5V | IBP _{-5VSHORTMax} | Absolute maximum output current when shorted to -5V |
| IBM _{-5VSHORTMax} | Absolute maximum current when BM is shorted to -5V | IBM _{-5VSHORTMax} | Absolute maximum output current when shorted to -5V |
| IBP _{27VSHORTMax} | Absolute maximum current when BP is shorted to 27V | IBP _{BAT27VSHORTMax} | Absolute maximum output current when shorted to 27V |
| IBM _{27VSHORTMax} | Absolute maximum current when BM is shorted to 27V | IBM _{BAT27VSHORTMax} | Absolute maximum output current when shorted to 27V |



Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|------------------------------------|--|--|---|
| Symbol | Parameter | Name | Description |
| $I_{BP48VShortMax}$ | Absolute maximum current when BP is shorted to 48V | $I_{BP_{BAT48VShortMax}}$ | Absolute maximum output current when shorted to 48V |
| $I_{BM48VShortMax}$ | Absolute maximum current when BM is shorted to 48V | $I_{BM_{BAT48VShortMax}}$ | Absolute maximum output current when shorted to 48V |
| t_{TxD_BUS01} | Delay time from TxD to BUS positive edge | $d_{BDT_{Tx10}}$ | Transmitter delay, negative edge |
| t_{TxD_BUS10} | Delay time from TxD to BUS negative edge | $d_{BDT_{Tx01}}$ | Transmitter delay, positive edge |
| $t_{TxD_MISMATCH}$ | Delay time from TxD to BUS mismatch | d_{TxAsym} | Transmitter delay mismatch $d_{BDT_{Tx10}} - d_{BDT_{Tx01}}$ |
| t_{BUS10} | Fall time differential bus voltage | $d_{BusTx10}$ | Fall time differential bus voltage (80% @ 20%) |
| t_{BUS01} | Rise time differential bus voltage | $d_{BusTx01}$ | Rise time differential bus voltage (20% @ 80%) |
| $t_{TxEN_BUS_Idle_Active}$ | Delay time from TxEN to bus active | $d_{BDT_{xia}}$ | Propagation delay idle @ active |
| $t_{TxEN_BUS_Active_Idle}$ | Delay time from TxEN to bus idle | $d_{BDT_{xai}}$ | Propagation delay active @ idle |
| $t_{TxEN_MISMATCH}$ | Delay time from TxEN to bus mismatch | $d_{BDT_{xDM}}$ | $d_{BDT_{xia}} - d_{BDT_{xai}}$ |
| $t_{BGE_BUS_Idle_Active}$ | Delay time from BGE to bus active | $d_{BDT_{xia}}$ | Propagation delay idle @ active |
| $t_{BGE_BUS_Active_Idle}$ | Delay time from BGE to bus idle | $d_{BDT_{xai}}$ | Propagation delay active @ idle |
| $t_{BUS_Idle_Active}$ | Differential bus voltage transition time: idle to active | $d_{BusTxia}$ | Transition time idle @ active |
| $t_{BUS_Active_Idle}$ | Differential bus voltage transition time: active to idle | $d_{BusTxai}$ | Transition time active → idle |
| $t_{TxEN_timeout}$ | TxEN timeout | - | - |
| Receiver | | | |
| R_{BP}, R_{BM} | BP, BM input resistance | RCM1, RCM2 | Receiver common mode input resistance |
| R_{DIFF} | BP, BM differential input resistance | - | - |
| V_{BPidle}, V_{BMidle} | Idle voltage in non-low-power modes on pin BP, BM | uBias | Bus bias voltage during BD_Normal mode |
| $V_{BPidle_low}, V_{BMidle_low}$ | | | Bus bias voltage during low-power modes |
| I_{BPidle} | Absolute idle output current on pin BP | - | - |
| I_{BMidle} | Absolute idle output current on pin BM | - | - |
| I_{BPleak}, I_{BMleak} | Absolute leakage current, when not powered | i_{BPLeak}, i_{BMLeak} | Absolute leakage current, when not powered |



Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|----------------------------|---|--|--|
| Symbol | Parameter | Name | Description |
| $V_{BUSActiveHigh}$ | Activity detection differential input voltage high | uBusActiveHigh | Upper Receiver threshold for detecting activity |
| $V_{BUSActiveLow}$ | Activity detection differential input voltage low | uBusActiveLow | Lower Receiver threshold for detecting activity |
| V_{Data1} | Data1 detection differential input voltage | uData1 | Receiver threshold for detecting Data_1 |
| V_{Data0} | Data0 detection differential input voltage | uData0 | Receiver threshold for detecting Data_0 |
| $V_{DataErr}$ | Mismatch between Data0 and Data1 differential input voltage | uData | Mismatch of Receiver thresholds |
| $V_{RECEIVE_COM}$ | Maximum common mode voltage range when receiving | uCM | Common mode voltage range (with respect to GND) that does not disturb the receive function |
| t_{BUS_RxD10} | Delay from bus to RxD negative edge | dBDRx10 | Receiver delay, negative edge |
| t_{BUS_RxD01} | Delay from bus to RxD positive edge | dBDRx01 | Receiver delay, positive edge |
| t_{BIT} | Bit time | - | - |
| t_{RxD_ASYM} | Delay time from bus to RxD mismatch | dRxAsym | Receiver delay mismatch dBDRx10 – dBDRx01 |
| t_{RxD_FALL} | Fall time RxD voltage | dRxSlope | Fall and rise time 20%-80% |
| t_{RxD_RISE} | Rise time RxD voltage | dRxSlope | Fall and rise time 20%-80% |
| $t_{BUSIdleDetection}$ | Idle detection time | dIdleDetection | Filter-time for idle detection |
| $t_{BUSActivityDetection}$ | Activity detection time | dActivityDetection | Filter-time for activity detection |
| $t_{BUSIdleReaction}$ | Idle reaction time | dBDRxai | Idle reaction time |
| $t_{BUSActivityReaction}$ | Activity reaction time | dBDRxia | Activity reaction time |
| Wake-Up Detector | | | |
| t_{BWU_D0} | Data0 detection time in remote wake-up pattern | dWU0Detect | Acceptance timeout for detection of a Data_0 phase in wake-up pattern |
| t_{BWU_Idle} | Idle or Data1 detection time in remote wake-up pattern | dWUIdleDetect | Acceptance timeout for detection of a Idle phase in wake-up pattern |
| t_{BWU_Detect} | Total remote wake-up detection time | dWUTimeout | Acceptance timeout for wake-up pattern recognition |
| V_{BWUTH} | Bus wake-up detection threshold | - | - |
| V_{LWUTH} | Local wake-up detection threshold | - | - |



Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|-------------------------------|---|--|--|
| Symbol | Parameter | Name | Description |
| I_{LWUL} | Low level input current on local WAKE pin | - | - |
| I_{LWUH} | High level input current on local WAKE pin | - | - |
| $t_{LWUFilter}$ | Local wake filter time | dWakePulseFilter | Wake pulse filter time (spike rejection) |
| - | V_{BAT} operating range $V_{BAT} = +6.5$ to $+50V$ | V_{BAT} for WU detector | Battery voltage required for wake-up detector operation |
| Supply Voltage Monitor | | | |
| V_{BATTHH} | V_{BAT} undervoltage recovery threshold | - | - |
| V_{BATTHL} | V_{BAT} undervoltage detection threshold | uUVBAT | Undervoltage detection threshold |
| V_{CCTHH} | V_{CC} undervoltage recovery threshold | - | - |
| V_{CCTHL} | V_{CC} undervoltage detection threshold | uUVCC | Undervoltage detection threshold |
| V_{IOTHH} | V_{IO} undervoltage recovery threshold | - | - |
| V_{IOTHL} | V_{IO} undervoltage detection threshold | uUVIO | Undervoltage detection threshold |
| t_{UV_DETECT} | Detection time for undervoltage at V_{BAT} , V_{CC} , V_{IO} | dUVBAT, dUVCC, dUVIO | Undervoltage reaction time |
| t_{UV_REC} | Detection time for undervoltage recovery at V_{BAT} , V_{CC} , V_{IO} | - | - |
| Bus Error Detection | | | |
| I_{THL} | Absolute bus current for low current detection | - | - |
| I_{THH} | Absolute bus current for high current detection | - | - |
| V_{SHORT} | Differential voltage on BP and BM for detecting short circuit between bus lines | - | - |
| t_{BUS_ERROR} | Bus error detection time | - | Detection only required while actively transmitting a data frame, error indication to host latest when transmission stops. |
| Over Temperature | | | |
| OT_{TH} | Over temperature threshold | - | - |
| OT_{TL} | Over temperature hysteresis | - | - |



Table 12. Comparison Table

| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|---|---|--|--|
| Symbol | Parameter | Name | Description |
| Power Supply Interface | | | |
| ΔV_{OINH} | High level voltage drop on INH1, INH2 | - | - |
| $ I_{IL} $ | Leakage current | - | - |
| Communication Controller Interface | | | |
| V_{TxDIH} | Threshold for detecting TxD as on logical high | $\mu VIO-IN-HIGH$ | Threshold for detecting a digital input as on logical high |
| V_{TxDIL} | Threshold for detecting TxD as on logical low | $\mu VIO-IN-LOW$ | Threshold for detecting a digital input as on logical low |
| I_{TxDIH} | TxD high level input current | - | - |
| I_{TxDIL} | TxD low level input current | - | - |
| V_{TxENIH} | Threshold for detecting TxEN as on logical high | $\mu VIO-IN-HIGH$ | Threshold for detecting a digital input as on logical high |
| V_{TxENIL} | Threshold for detecting TxEN as on logical low | $\mu VIO-IN-LOW$ | Threshold for detecting a digital input as on logical low |
| I_{TxENIH} | TxEN high level input current | - | - |
| I_{TxENIL} | TxEN low level input current | - | - |
| V_{RxDOH} | RxD high level output voltage | $\mu VIO-OUT-HIGH$ | Output voltage on a digital output, when in logical high state |
| V_{RxDOL} | RxD low level output voltage | $\mu VIO-OUT-LOW$ | Output voltage on a digital output, when in logical low state |
| Host Interface | | | |
| V_{STBNIH} | Threshold for detecting STBN as on logical high | $\mu VIO-IN-HIGH$ | Threshold for detecting a digital input as on logical high |
| V_{STBNIL} | Threshold for detecting STBN as on logical low | $\mu VIO-IN-LOW$ | Threshold for detecting a digital input as on logical low |
| I_{STBNIH} | STBN high level input current | - | - |
| I_{STBNIL} | STBN low level input current | - | - |
| $t_{STBN_DEB_LP}$ | STBN de-bouncing time low-power modes | - | - |
| $t_{STBN_DEB_NLP}$ | STBN de-bouncing time non-low-power modes | - | - |
| V_{ENIH} | Threshold for detecting EN as on logical high | $\mu VIO-IN-HIGH$ | Threshold for detecting a digital input as on logical high |



Table 12. Comparison Table

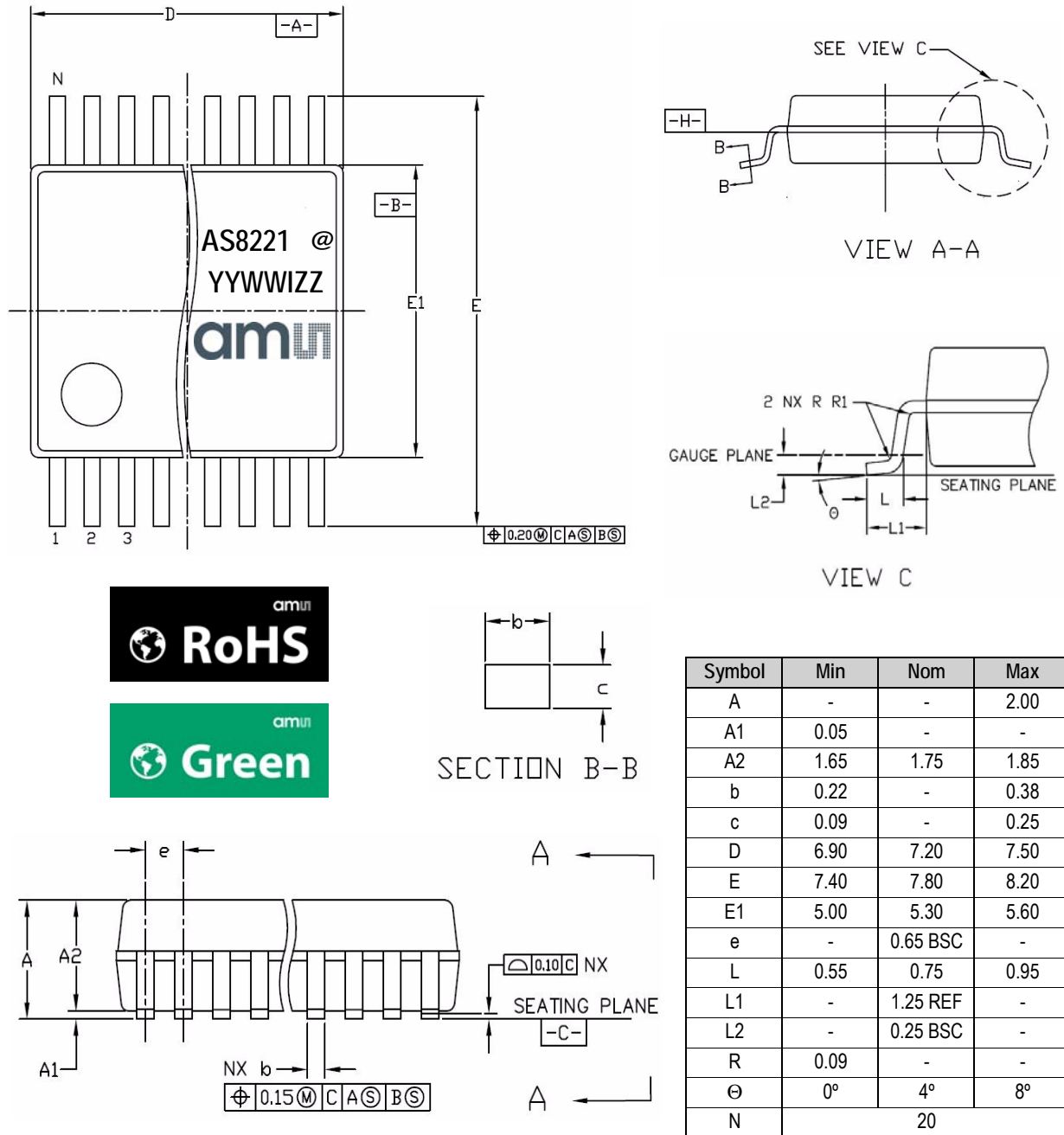
| AS8221 Datasheet | | FlexRay Electrical Physical Layer Specification V2.1 Rev. B | |
|-------------------------------|--|--|--|
| Symbol | Parameter | Name | Description |
| V_{ENIL} | Threshold for detecting EN as on logical low | $\mu VIO-IN-LOW$ | Threshold for detecting a digital input as on logical low |
| I_{ENIH} | EN high level input current | - | - |
| I_{ENIL} | EN low level input current | - | - |
| $t_{EN_DEB_LP}$ | EN de-bouncing time low-power modes | - | - |
| $t_{EN_DEB_NLP}$ | EN de-bouncing time non-low-power modes | - | - |
| V_{ERRNOH} | ERRN high level output voltage | $\mu VIO-OUT-HIGH$ | Output voltage on a digital output, when in logical high state |
| V_{ERRNOL} | ERRN low level output voltage | $\mu VIO-OUT-LOW$ | Output voltage on a digital output, when in logical low state |
| Bus Guardian Interface | | | |
| V_{BGEIH} | Threshold for detecting BGE as on logical high | $\mu VIO-IN-HIGH$ | Threshold for detecting a digital input as on logical high |
| V_{BGEIL} | Threshold for detecting BGE as on logical low | $\mu VIO-IN-LOW$ | Threshold for detecting a digital input as on logical low |
| I_{BGEIH} | BGE high level input current | - | - |
| I_{BGEIL} | BGE low level input current | - | - |
| V_{RXENOH} | RxEN high level output voltage | $\mu VIO-OUT-HIGH$ | Output voltage on a digital output, when in logical high state |
| V_{RXENOL} | RxEN low level output voltage | $\mu VIO-OUT-LOW$ | Output voltage on a digital output, when in logical low state |
| Read Out Interface | | | |
| $t_{RO_EN_ERRN}$ | Propagation delay falling edge EN to ERRN | - | - |
| $t_{RO_EN_TIMEOUT}$ | Error-read-out timeout | - | - |



11 Package Drawings and Markings

The device is available in a SSOP20 Package.

Figure 21. Package Drawings and Dimensions



Notes:

1. Dimensions and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.

Marking Information:

| YY | WW | I | ZZ | @ |
|-------------------------------------|--------------------|---------------------------|----------------------------|-------------------|
| Last two digits of the current year | Manufacturing Week | Assembly plant identifier | Assembly traceability code | Sublot identifier |



Revision History

| Revision | Date | Owner | Description |
|----------|---------------|-------|--|
| 1.0 | Sep 01, 2009 | | First version |
| 1.1 | Sep 14, 2009 | | Made sentence corrections and converted the 'Typ' values of Table 3 in to standard format. No Technical Changes to the datasheet. |
| 1.2 | May 13, 2010 | hgl | Updated the ERRN Signalling Table 8 . (no functional change) |
| | | | Updated Ordering Information Table 13 . |
| | | | Added Package Drawings and Markings – refer to page 39. |
| 1.3 | July 16, 2010 | | Updated Ordering Information Table 13 . |
| 1.4 | Oct 30, 2010 | hgl | Updated the following: VBAT minimum voltage requirement in Electrical Characteristics, Error Flags, Error and Status Flag Bit Order. |
| | Nov 18, 2010 | | Updated Absolute Maximum Ratings on page 6 , Package Drawings and Markings on page 39 . |
| | Dec 15, 2010 | | Updated package body temperature under Absolute Maximum Ratings. |
| 1.5 | Feb 24, 2011 | | Figure 12 , Figure 13 , Figure 14 , Figure 15 , Figure 16 updated. Added Application Circuits. |
| 1.6 | Dec 19, 2011 | | Updated ESD parameter in Absolute Maximum Ratings on page 6 . |
| 1.7 | Feb 16, 2012 | | Updated Package Drawings and Markings section. |
| 1.8 | Jan 11, 2013 | | Updated Ordering Information. |

Note: Typos may not be explicitly mentioned under revision history.



12 Ordering Information

The devices are available as the standard products shown in [Table 13](#).

Table 13. Ordering Information

| Ordering Code | Marking | Description | Delivery Form | Package |
|---------------|---------|-------------------------------------|--|---------|
| AS8221-ASSP | AS8221 | AS8221 FlexRay Standard Transceiver | Tape & Reel in Dry Pack (1 reel = 2000 units) | SSOP-20 |
| AS8221-ASSM | AS8221 | | Tape & Reel in Dry Pack (1 reel = 500 units) | SSOP-20 |

Note: All products are RoHS compliant and ams green.
Buy our products or get free samples online at www.ams.com/ICdirect

Technical Support is available at www.ams.com/Technical-Support

For further information and requests, email us at sales@ams.com
(or) find your local distributor at www.ams.com/distributor



Copyrights

Copyright © 1997-2013, ams AG, Tobelbaderstrasse 30, 8141 Unterpremstaetten, Austria-Europe. Trademarks Registered ®. All rights reserved. The material herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner.

All products and companies mentioned are trademarks or registered trademarks of their respective companies.

Disclaimer

Devices sold by ams AG are covered by the warranty and patent indemnification provisions appearing in its Term of Sale. ams AG makes no warranty, express, statutory, implied, or by description regarding the information set forth herein or regarding the freedom of the described devices from patent infringement. ams AG reserves the right to change specifications and prices at any time and without notice. Therefore, prior to designing this product into a system, it is necessary to check with ams AG for current information. This product is intended for use in normal commercial applications. Applications requiring extended temperature range, unusual environmental requirements, or high reliability applications, such as military, medical life-support or life-sustaining equipment are specifically not recommended without additional processing by ams AG for each application. For shipments of less than 100 parts the manufacturing flow might show deviations from the standard production flow, such as test flow or test location.

The information furnished here by ams AG is believed to be correct and accurate. However, ams AG shall not be liable to recipient or any third party for any damages, including but not limited to personal injury, property damage, loss of profits, loss of use, interruption of business or indirect, special, incidental or consequential damages, of any kind, in connection with or arising out of the furnishing, performance or use of the technical data herein. No obligation or liability to recipient or any third party shall arise or flow out of ams AG rendering of technical or other services.



Contact Information

Headquarters

ams AG
Tobelbaderstrasse 30
A-8141 Unterpremstaetten, Austria

Tel : +43 (0) 3136 500 0
Fax : +43 (0) 3136 525 01

For Sales Offices, Distributors and Representatives, please visit:

<http://www.ams.com/contact>

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- [View AS8221-ASSP on WIN SOURCE](#)
- [OSRAM Opto Semiconductors Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management